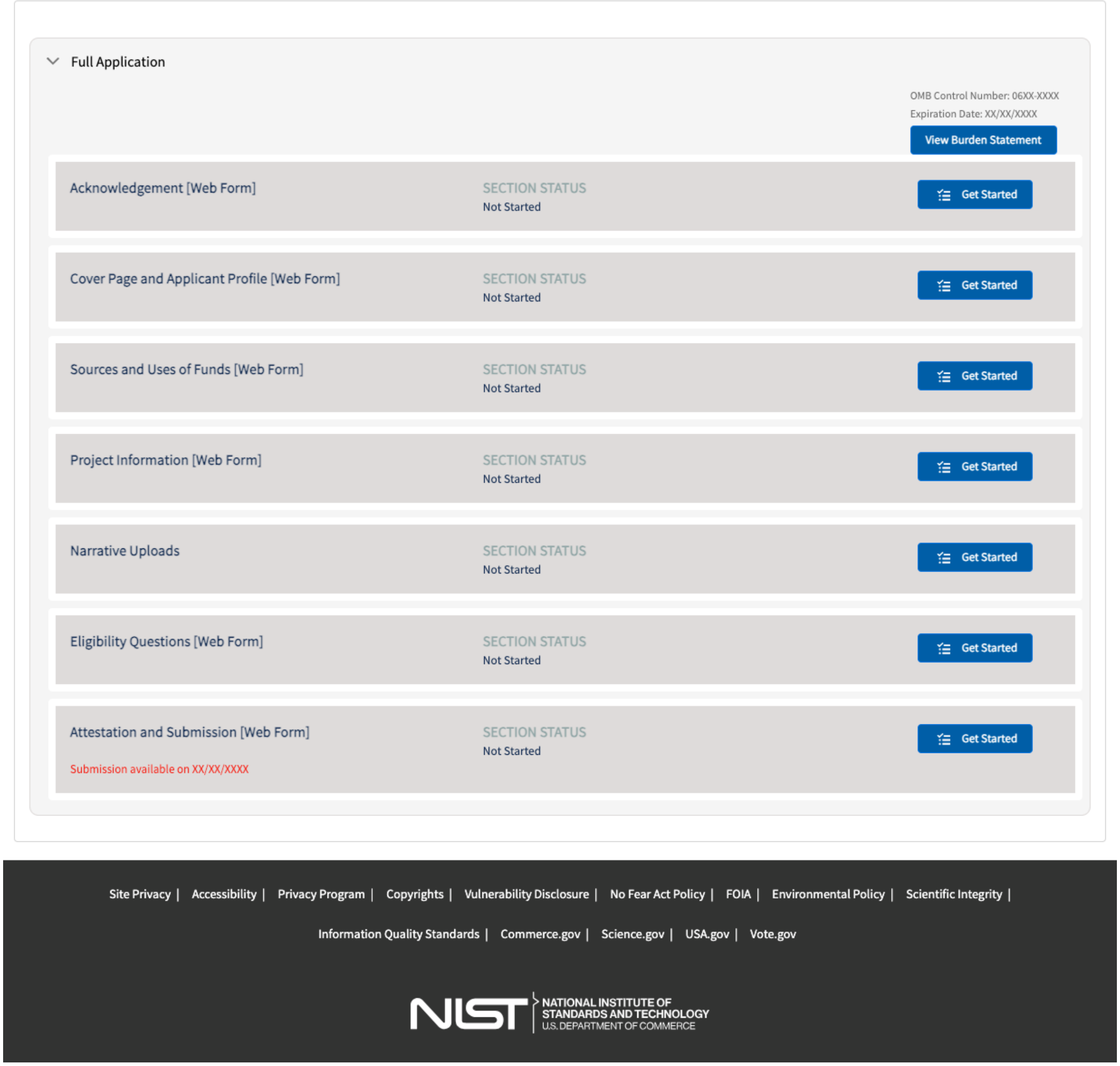
NOFO3 Full Application

Landing Page

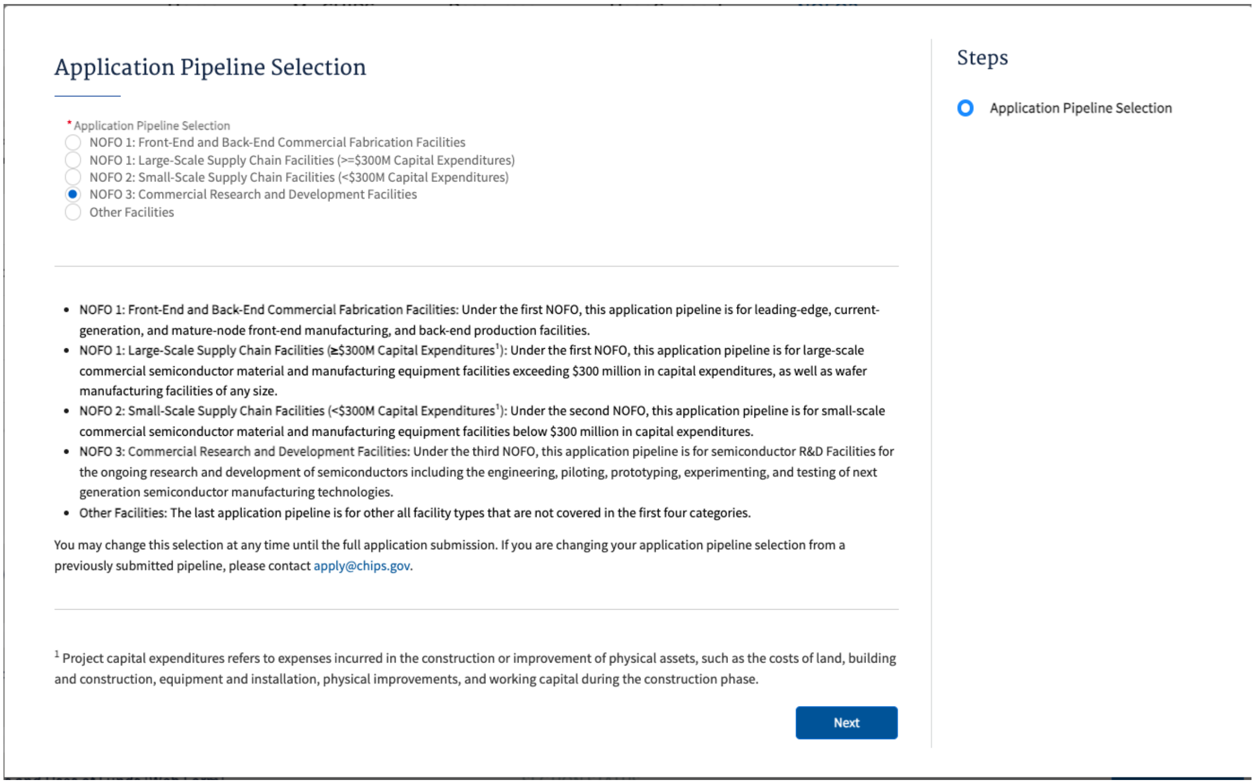


Full Application

OMB Control Number: 06XX-XXXX
Expiration Date: XX/XX/XXXX

Acknowledgement [Web Form]	SECTION STATUS Not Started	Get Started
Cover Page and Applicant Profile [Web Form]	SECTION STATUS Not Started	Get Started
Sources and Uses of Funds [Web Form]	SECTION STATUS Not Started	Get Started
Project Information [Web Form]	SECTION STATUS Not Started	Get Started
Narrative Uploads	SECTION STATUS Not Started	Get Started
Eligibility Questions [Web Form]	SECTION STATUS Not Started	Get Started
Attestation and Submission [Web Form] Submission available on XX/XX/XXXX	SECTION STATUS Not Started	Get Started

Pipeline Selection



Application Pipeline Selection

* Application Pipeline Selection

○ NOFO 1: Front-End and Back-End Commercial Fabrication Facilities
○ NOFO 1: Large-Scale Supply Chain Facilities (>=$300M Capital Expenditures)
○ NOFO 2: Small-Scale Supply Chain Facilities (<$300M Capital Expenditures)
● NOFO 3: Commercial Research and Development Facilities
○ Other Facilities

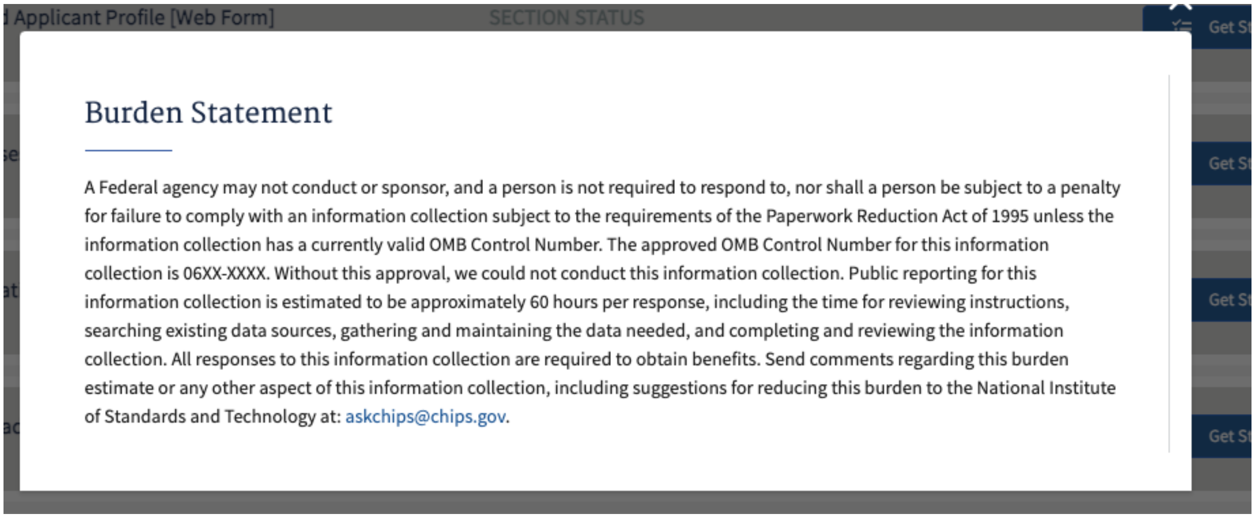
- NOFO 1: Front-End and Back-End Commercial Fabrication Facilities: Under the first NOFO, this application pipeline is for leading-edge, current-generation, and mature-node front-end manufacturing, and back-end production facilities.
- NOFO 1: Large-Scale Supply Chain Facilities (≥$300M Capital Expenditures[1]): Under the first NOFO, this application pipeline is for large-scale commercial semiconductor material and manufacturing equipment facilities exceeding $300 million in capital expenditures, as well as wafer manufacturing facilities of any size.
- NOFO 2: Small-Scale Supply Chain Facilities (<$300M Capital Expenditures[1]): Under the second NOFO, this application pipeline is for small-scale commercial semiconductor material and manufacturing equipment facilities below $300 million in capital expenditures.
- NOFO 3: Commercial Research and Development Facilities: Under the third NOFO, this application pipeline is for semiconductor R&D Facilities for the ongoing research and development of semiconductors including the engineering, piloting, prototyping, experimenting, and testing of next generation semiconductor manufacturing technologies.
- Other Facilities: The last application pipeline is for other all facility types that are not covered in the first four categories.

You may change this selection at any time until the full application submission. If you are changing your application pipeline selection from a previously submitted pipeline, please contact apply@chips.gov.

---

[1] Project capital expenditures refers to expenses incurred in the construction or improvement of physical assets, such as the costs of land, building and construction, equipment and installation, physical improvements, and working capital during the construction phase.

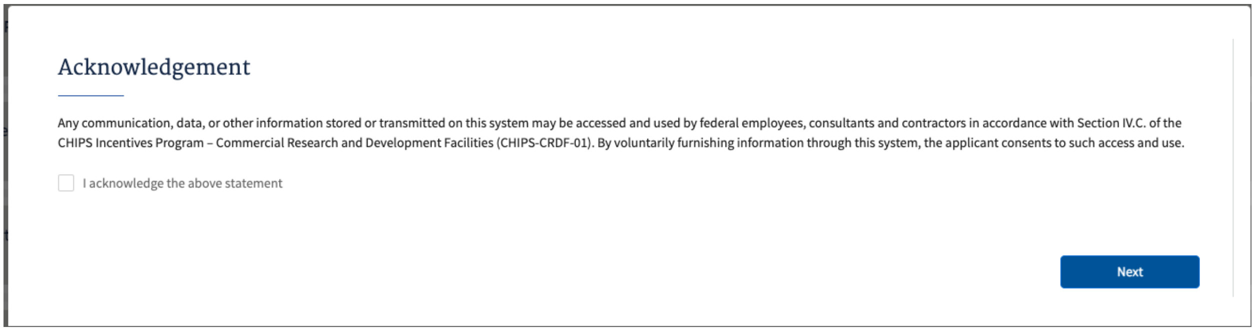
Burden Statement



Burden Statement

A Federal agency may not conduct or sponsor, and a person is not required to respond to, nor shall a person be subject to a penalty for failure to comply with an information collection subject to the requirements of the Paperwork Reduction Act of 1995 unless the information collection has a currently valid OMB Control Number. The approved OMB Control Number for this information collection is 06XX-XXXX. Without this approval, we could not conduct this information collection. Public reporting for this information collection is estimated to be approximately 60 hours per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the information collection. All responses to this information collection are required to obtain benefits. Send comments regarding this burden estimate or any other aspect of this information collection, including suggestions for reducing this burden to the National Institute of Standards and Technology at: askchips@chips.gov.

Acknowledgment

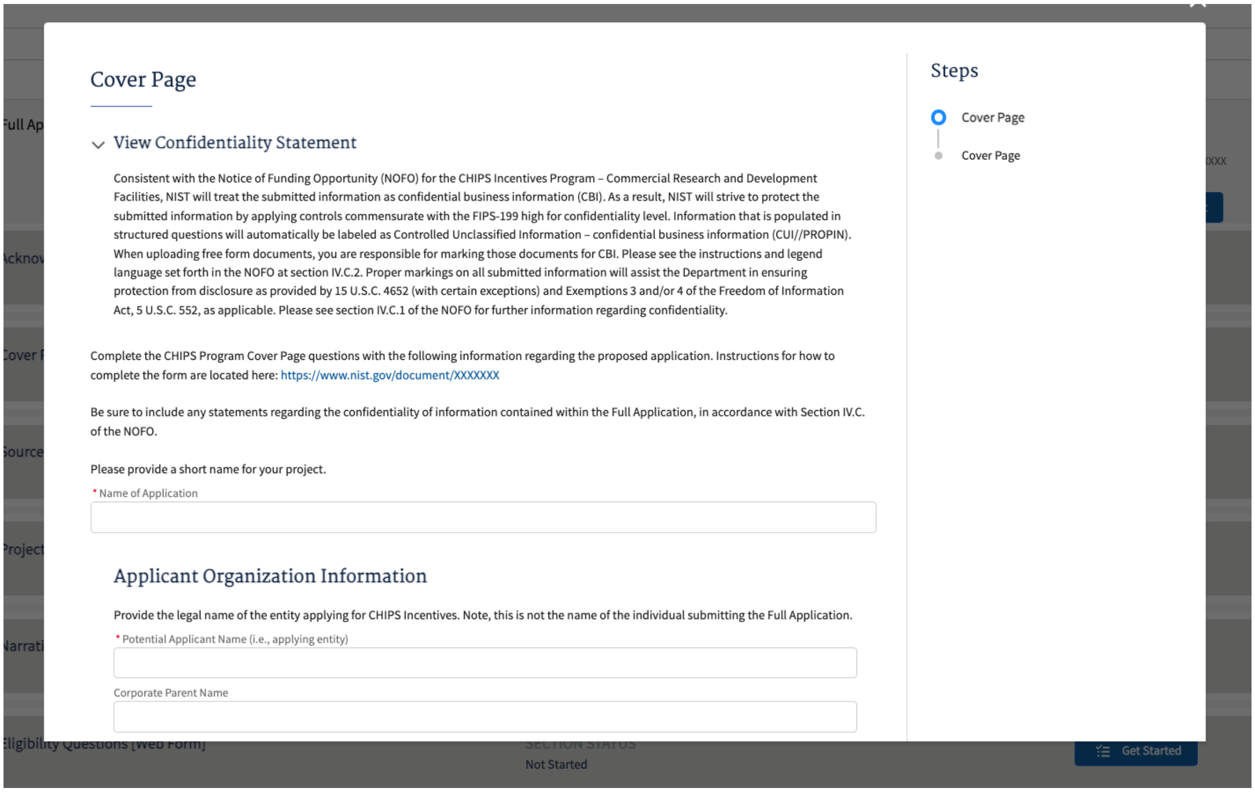


Acknowledgement

Any communication, data, or other information stored or transmitted on this system may be accessed and used by federal employees, consultants and contractors in accordance with Section IV.C. of the CHIPS Incentives Program – Commercial Research and Development Facilities (CHIPS-CRDF-01). By voluntarily furnishing information through this system, the applicant consents to such access and use.

☐ I acknowledge the above statement

Cover Page



Cover Page

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Complete the CHIPS Program Cover Page questions with the following information regarding the proposed application. Instructions for how to complete the form are located here: https://www.nist.gov/document/XXXXXXX

Be sure to include any statements regarding the confidentiality of information contained within the Full Application, in accordance with Section IV.C. of the NOFO.

Please provide a short name for your project.

* Name of Application

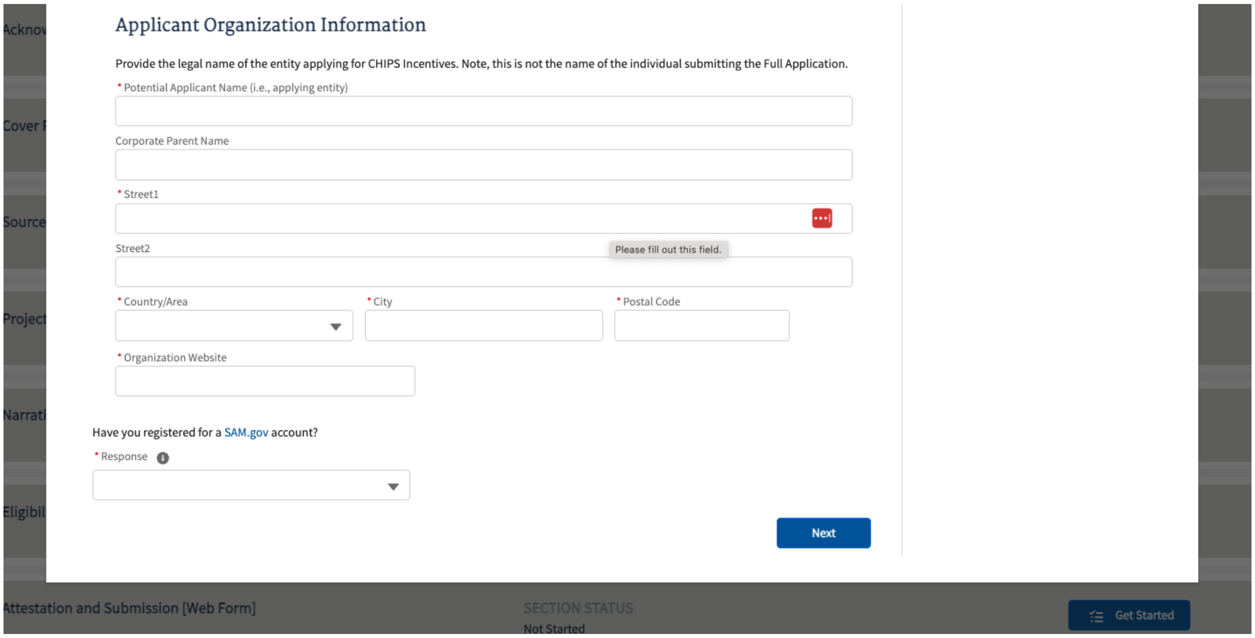
Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity)

Corporate Parent Name

Applicant Organization Information



Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity)

Corporate Parent Name

* Street1

Please fill out this field.

Street2

* Country/Area

* City

* Postal Code

* Organization Website

Have you registered for a SAM.gov account?

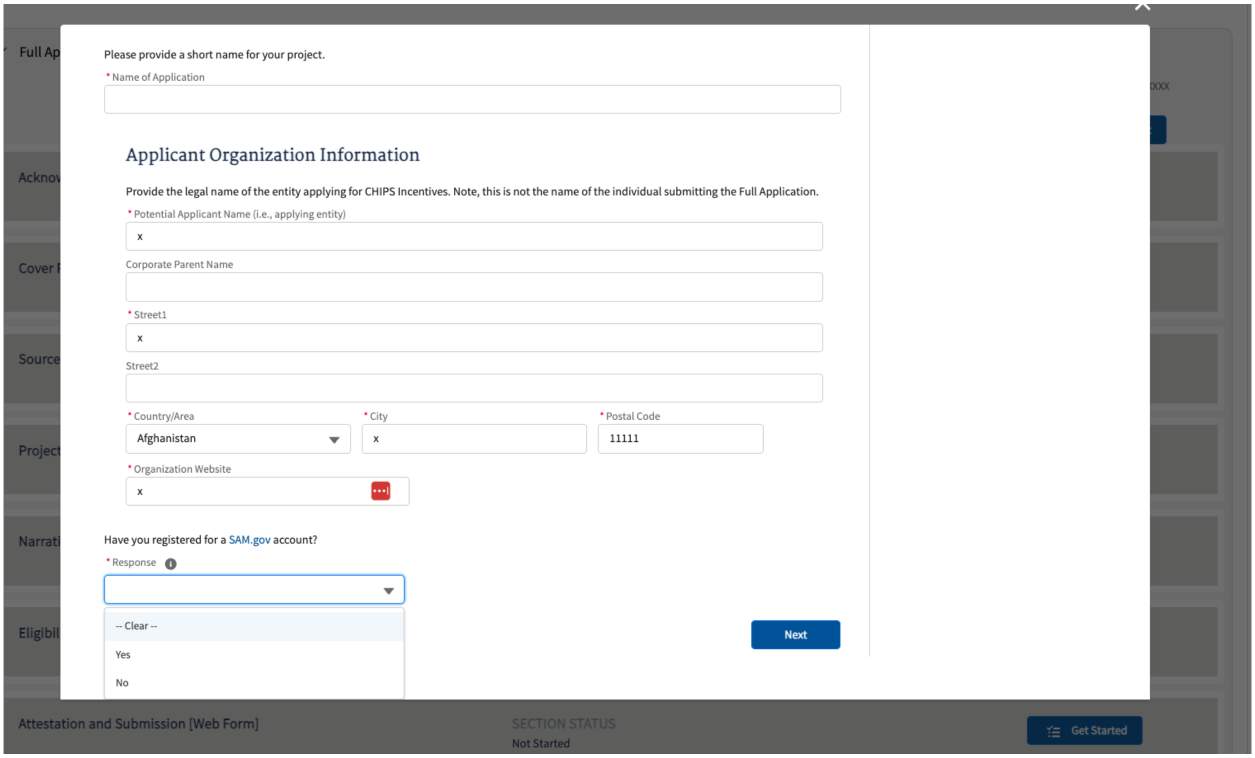
* Response

Attestation and Submission [Web Form]

SECTION STATUS

Not Started

Applicant Organization Information Continued



Please provide a short name for your project.

* Name of Application

Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity): x

Corporate Parent Name:

* Street1: x

Street2:

* Country/Area: Afghanistan

* City: x

* Postal Code: 11111

* Organization Website: x

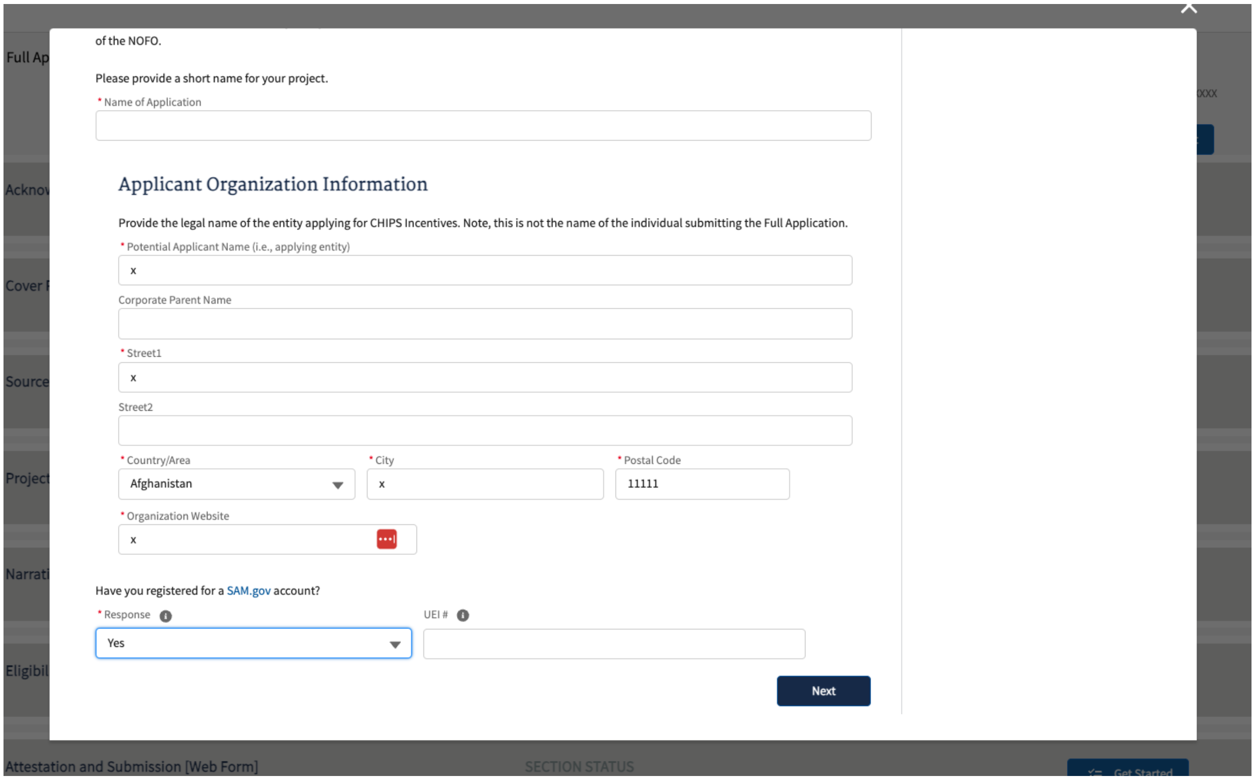
Have you registered for a SAM.gov account?

* Response

Picklist: Have you registered for a SAM.gov account?
Picklist Values:

- Yes
- No

Applicant Organization Information - *Have you registered for a Sam.gov account?* response is *Yes* shows *UEI#* field


of the NOFO.

Please provide a short name for your project.

* Name of Application

Applicant Organization Information

Provide the legal name of the entity applying for CHIPS Incentives. Note, this is not the name of the individual submitting the Full Application.

* Potential Applicant Name (i.e., applying entity): x

Corporate Parent Name:

* Street1: x

Street2:

* Country/Area: Afghanistan

* City: x

* Postal Code: 11111

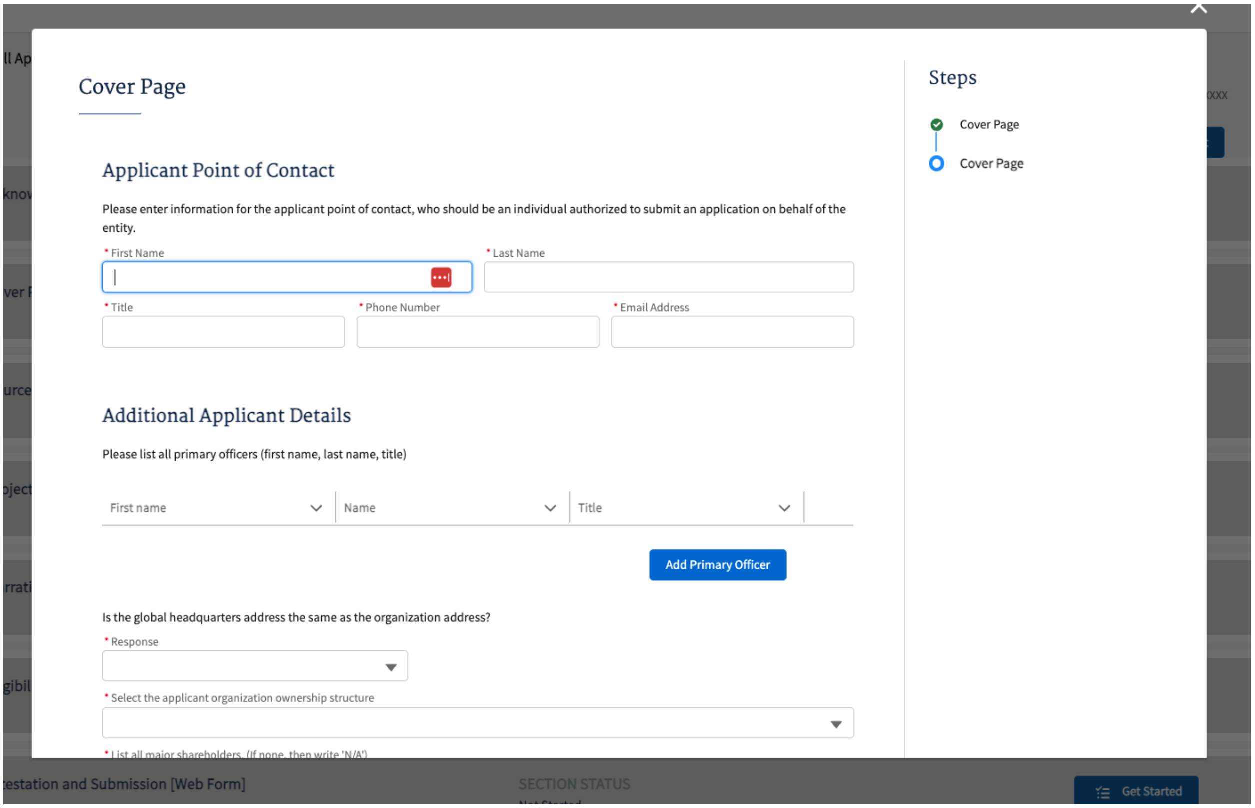
* Organization Website: x

Have you registered for a SAM.gov account?

* Response: Yes

UEI #:

Applicant Point of Contact



Cover Page

Applicant Point of Contact

Please enter information for the applicant point of contact, who should be an individual authorized to submit an application on behalf of the entity.

* First Name

* Last Name

* Title

* Phone Number

* Email Address

Additional Applicant Details

Please list all primary officers (first name, last name, title)

First name	Name	Title

Add Primary Officer

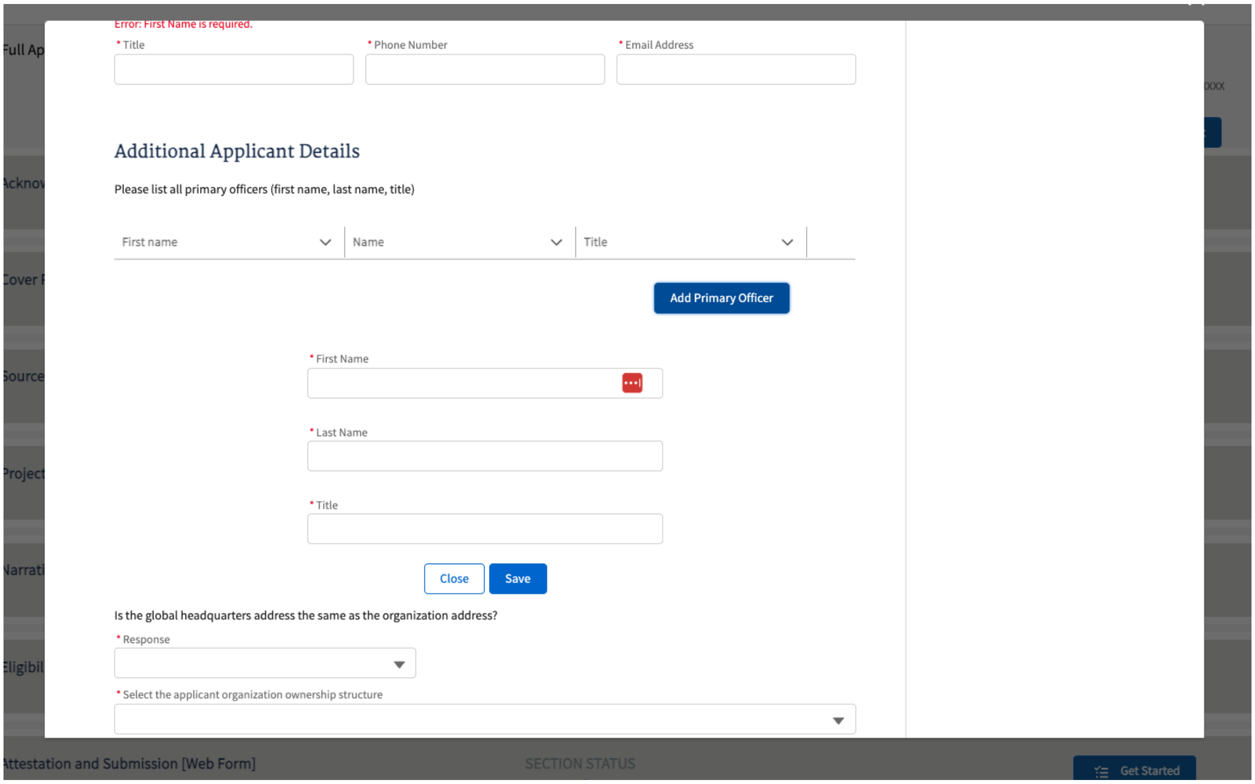
Is the global headquarters address the same as the organization address?

* Response

* Select the applicant organization ownership structure

* List all major shareholders. (If none, then write 'N/A')

Add Primary Officer



Error: First Name is required.

* Title

* Phone Number

* Email Address

Additional Applicant Details

Please list all primary officers (first name, last name, title)

First name	Name	Title

* First Name

* Last Name

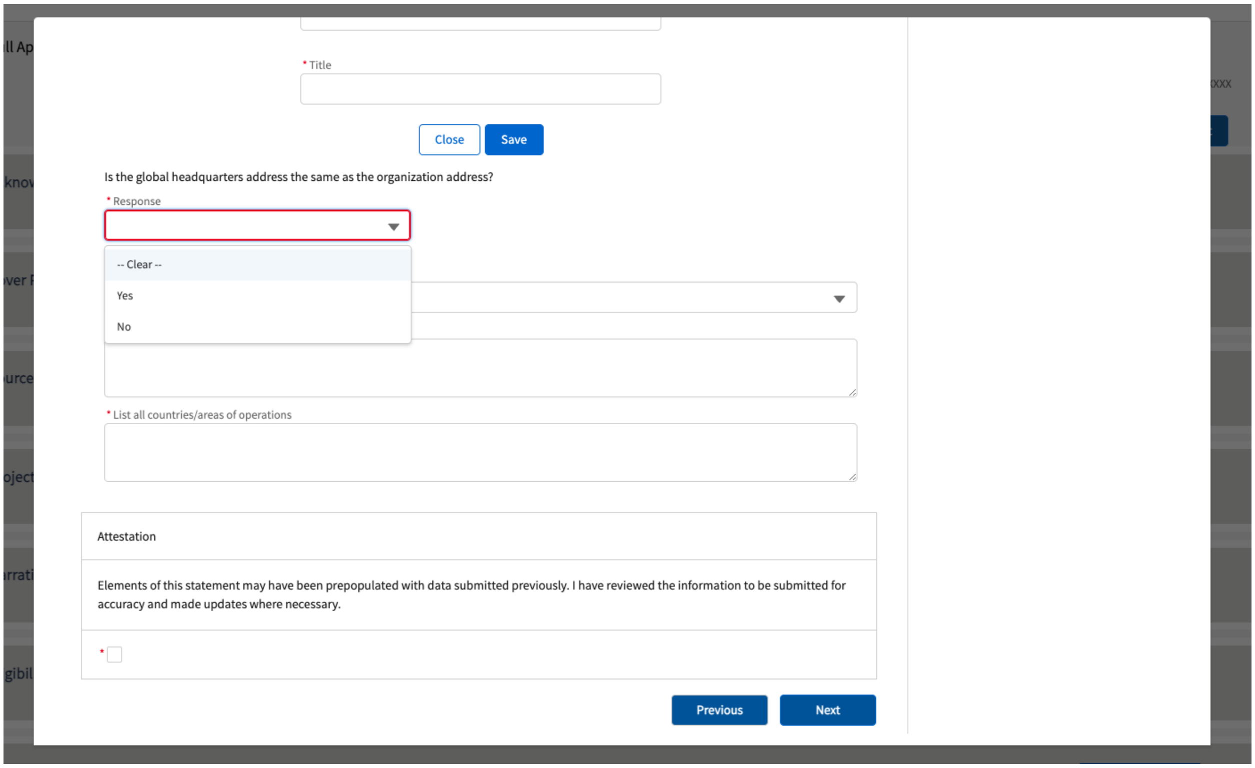
* Title

Is the global headquarters address the same as the organization address?

* Response

* Select the applicant organization ownership structure

Is Global Headquarters the same as the organization address?



* Title

Is the global headquarters address the same as the organization address?

* Response

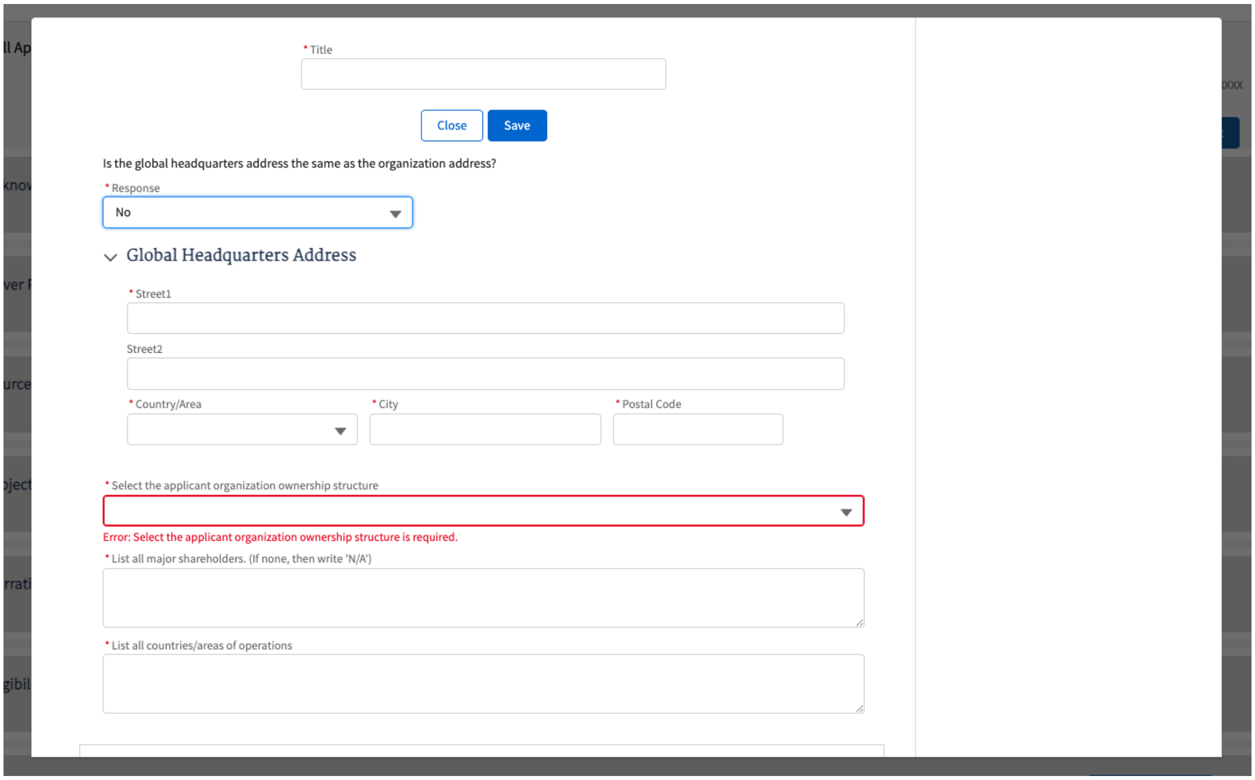
* List all countries/areas of operations

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

Is Global Headquarters the same as the organization address? Response is *No,* showing Global Address Headquarters input fields



* Title

Is the global headquarters address the same as the organization address?

* Response: No

Global Headquarters Address

* Street1

Street2

* Country/Area

* City

* Postal Code

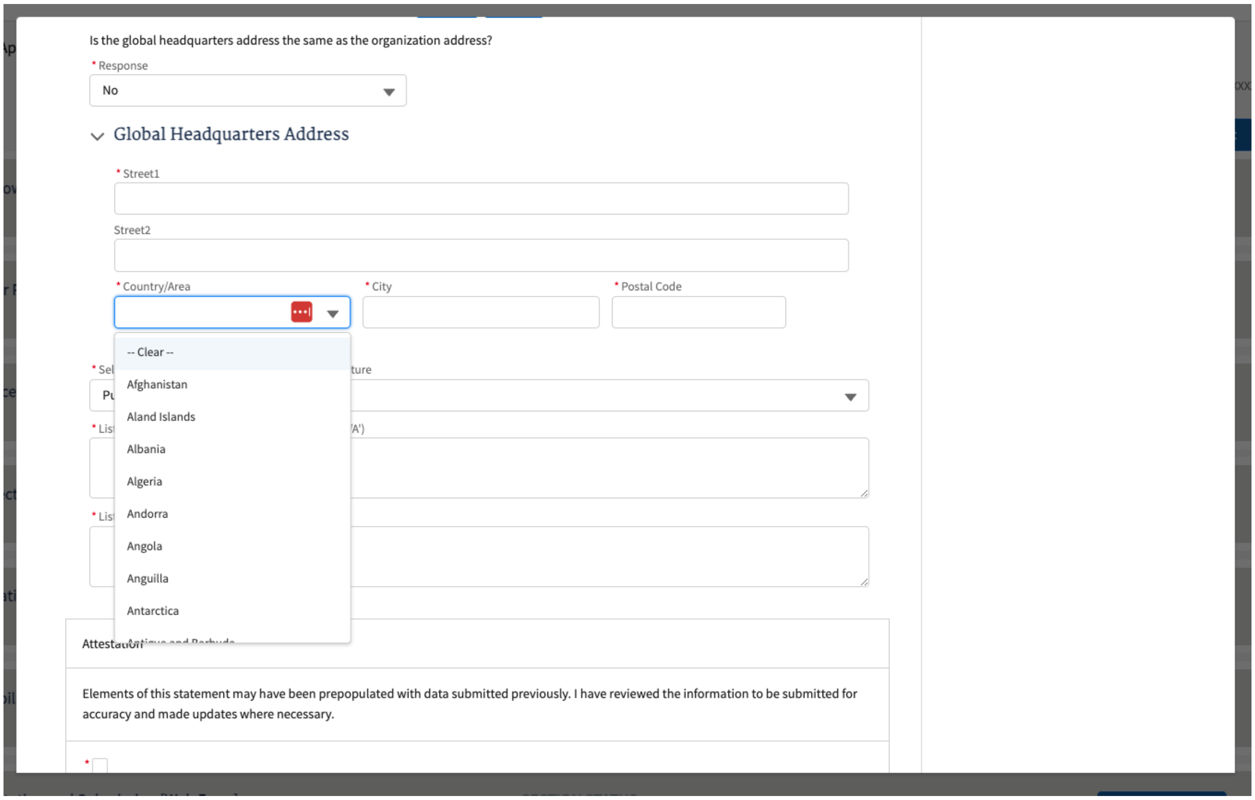
* Select the applicant organization ownership structure

Error: Select the applicant organization ownership structure is required.

* List all major shareholders. (If none, then write 'N/A')

* List all countries/areas of operations

Country/Area field selection



Is the global headquarters address the same as the organization address?

* Response

No

Global Headquarters Address

* Street1

Street2

* Country/Area

* City

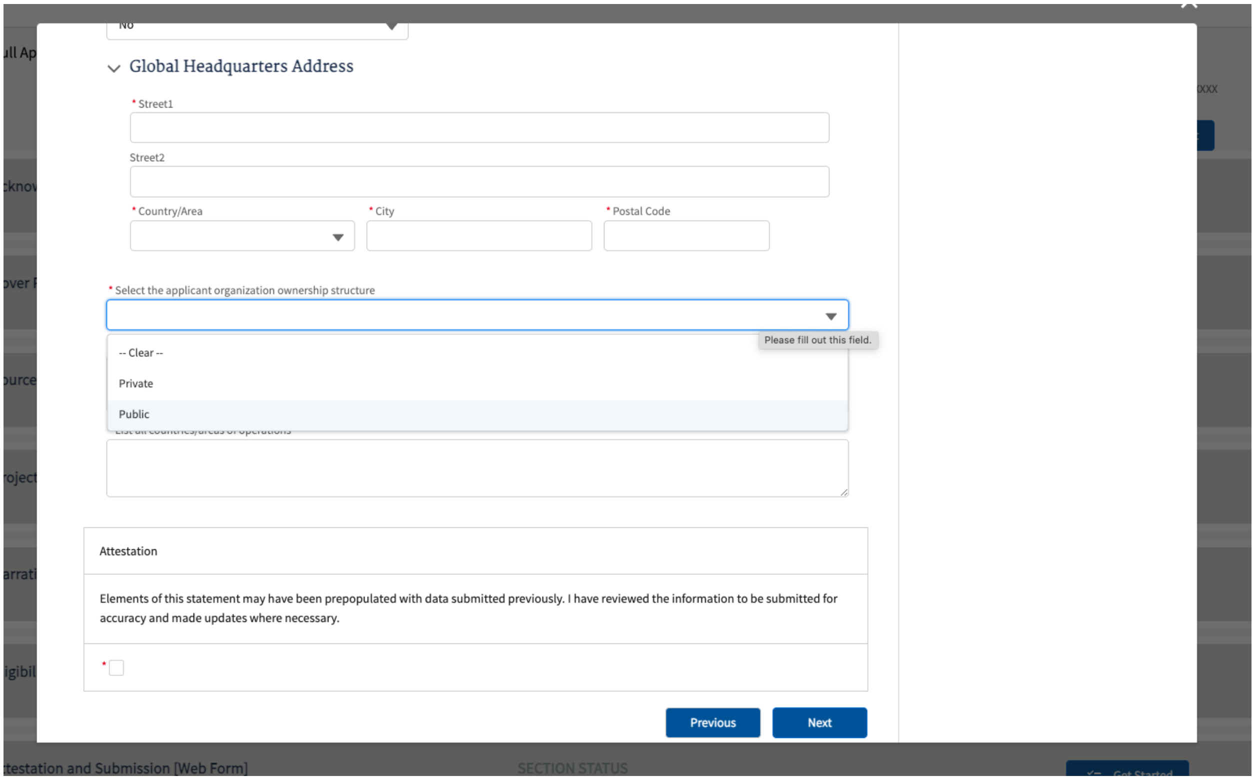
* Postal Code

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

Select the applicant organization ownership structure



Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

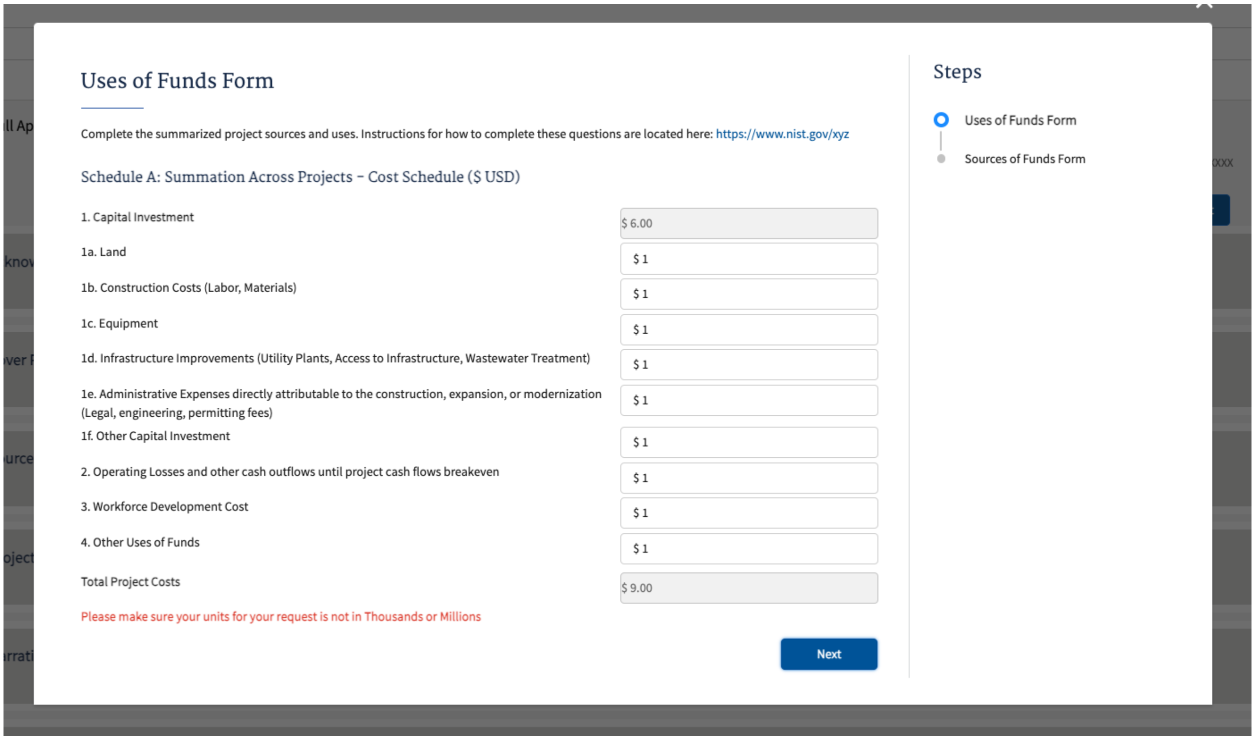
Picklist: Select the applicant organization ownership structure

Picklist Values:

- Private
- Public

Sources and Uses of Funds [Web Form]

Uses of Funds



Uses of Funds Form

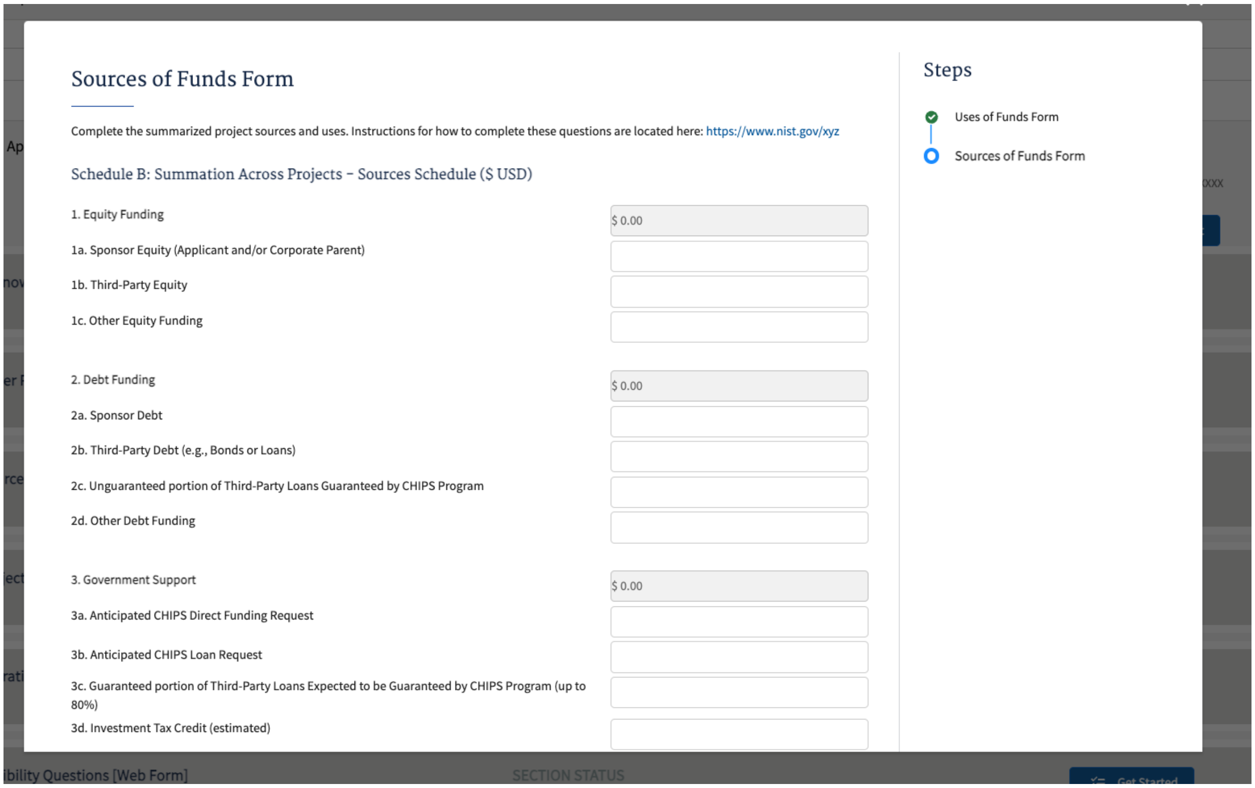
Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

Schedule A: Summation Across Projects – Cost Schedule ($ USD)

1. Capital Investment	$ 6.00
1a. Land	$ 1
1b. Construction Costs (Labor, Materials)	$ 1
1c. Equipment	$ 1
1d. Infrastructure Improvements (Utility Plants, Access to Infrastructure, Wastewater Treatment)	$ 1
1e. Administrative Expenses directly attributable to the construction, expansion, or modernization (Legal, engineering, permitting fees)	$ 1
1f. Other Capital Investment	$ 1
2. Operating Losses and other cash outflows until project cash flows breakeven	$ 1
3. Workforce Development Cost	$ 1
4. Other Uses of Funds	$ 1
Total Project Costs	$ 9.00

Please make sure your units for your request is not in Thousands or Millions

Sources of Funds



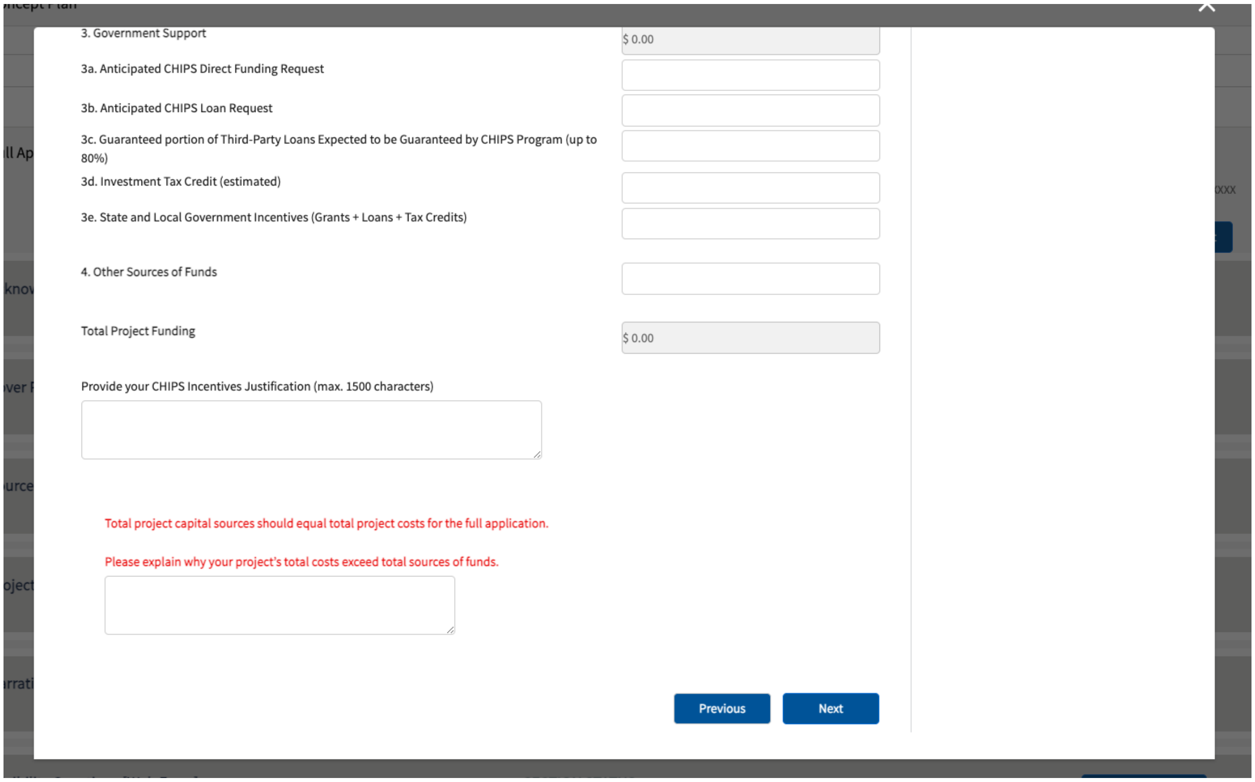
Sources of Funds Form

Complete the summarized project sources and uses. Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

Schedule B: Summation Across Projects – Sources Schedule ($ USD)

1. Equity Funding	$ 0.00
1a. Sponsor Equity (Applicant and/or Corporate Parent)	
1b. Third-Party Equity	
1c. Other Equity Funding	
2. Debt Funding	$ 0.00
2a. Sponsor Debt	
2b. Third-Party Debt (e.g., Bonds or Loans)	
2c. Unguaranteed portion of Third-Party Loans Guaranteed by CHIPS Program	
2d. Other Debt Funding	
3. Government Support	$ 0.00
3a. Anticipated CHIPS Direct Funding Request	
3b. Anticipated CHIPS Loan Request	
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	
3d. Investment Tax Credit (estimated)	

Sources of Funds Continued



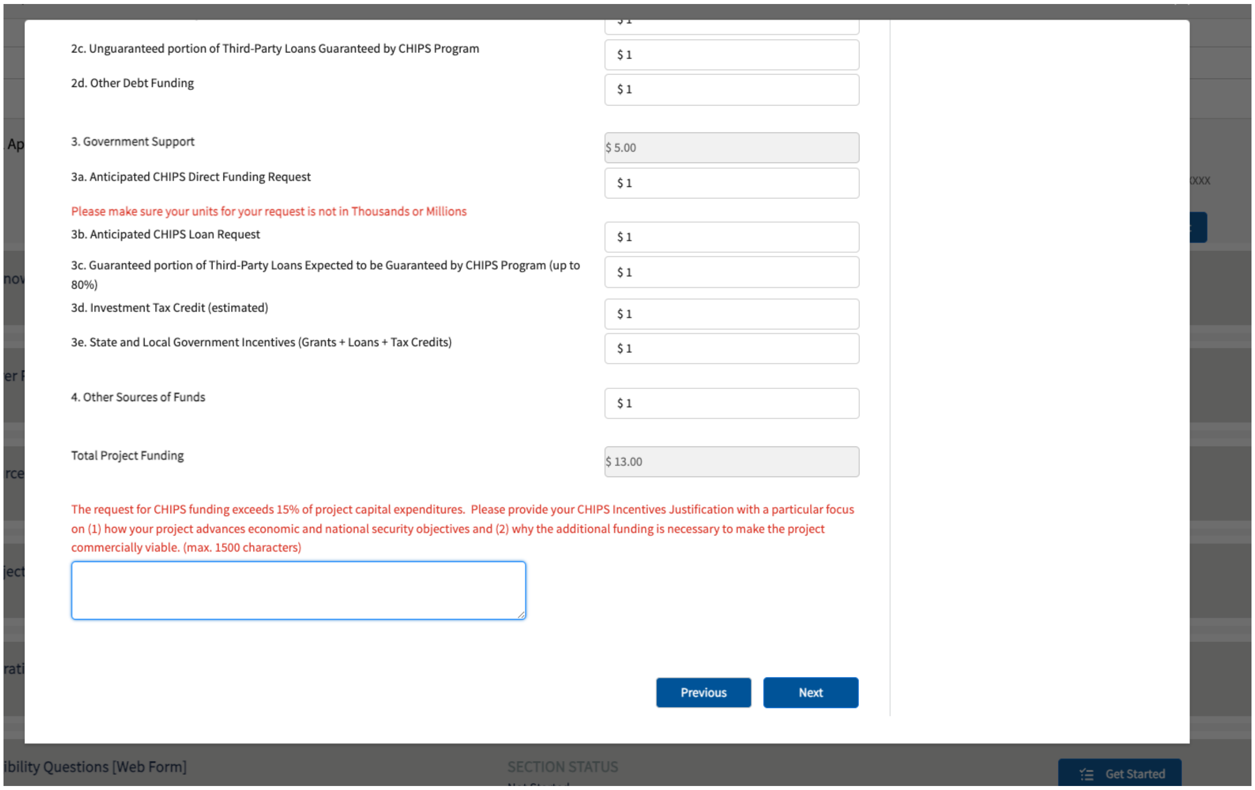
3. Government Support	$ 0.00
3a. Anticipated CHIPS Direct Funding Request	
3b. Anticipated CHIPS Loan Request	
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	
3d. Investment Tax Credit (estimated)	
3e. State and Local Government Incentives (Grants + Loans + Tax Credits)	
4. Other Sources of Funds	
Total Project Funding	$ 0.00

Provide your CHIPS Incentives Justification (max. 1500 characters)

Total project capital sources should equal total project costs for the full application.

Please explain why your project's total costs exceed total sources of funds.

Sources of Funds disclaimer regarding project capital expenditures



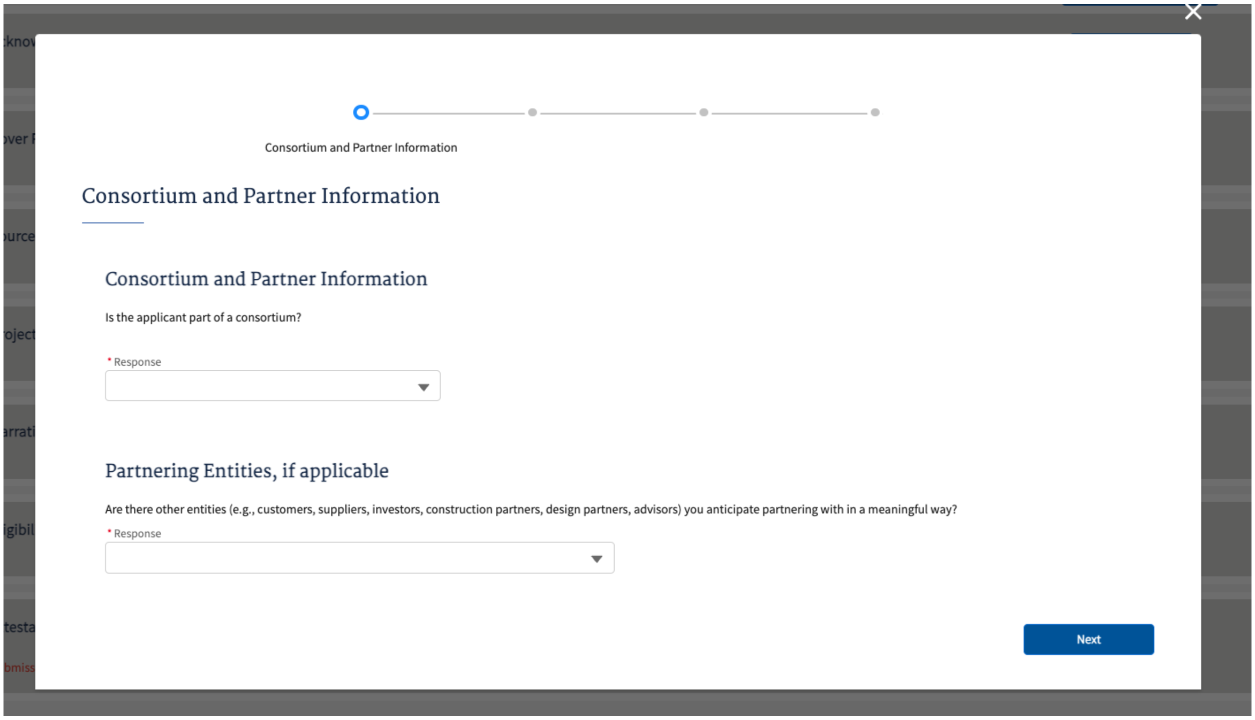
2c. Unguaranteed portion of Third-Party Loans Guaranteed by CHIPS Program	$ 1
2d. Other Debt Funding	$ 1
3. Government Support	$ 5.00
3a. Anticipated CHIPS Direct Funding Request	$ 1

Please make sure your units for your request is not in Thousands or Millions

3b. Anticipated CHIPS Loan Request	$ 1
3c. Guaranteed portion of Third-Party Loans Expected to be Guaranteed by CHIPS Program (up to 80%)	$ 1
3d. Investment Tax Credit (estimated)	$ 1
3e. State and Local Government Incentives (Grants + Loans + Tax Credits)	$ 1
4. Other Sources of Funds	$ 1
Total Project Funding	$ 13.00

The request for CHIPS funding exceeds 15% of project capital expenditures. Please provide your CHIPS Incentives Justification with a particular focus on (1) how your project advances economic and national security objectives and (2) why the additional funding is necessary to make the project commercially viable. (max. 1500 characters)

Consortium and Partner Information



Consortium and Partner Information

Consortium and Partner Information

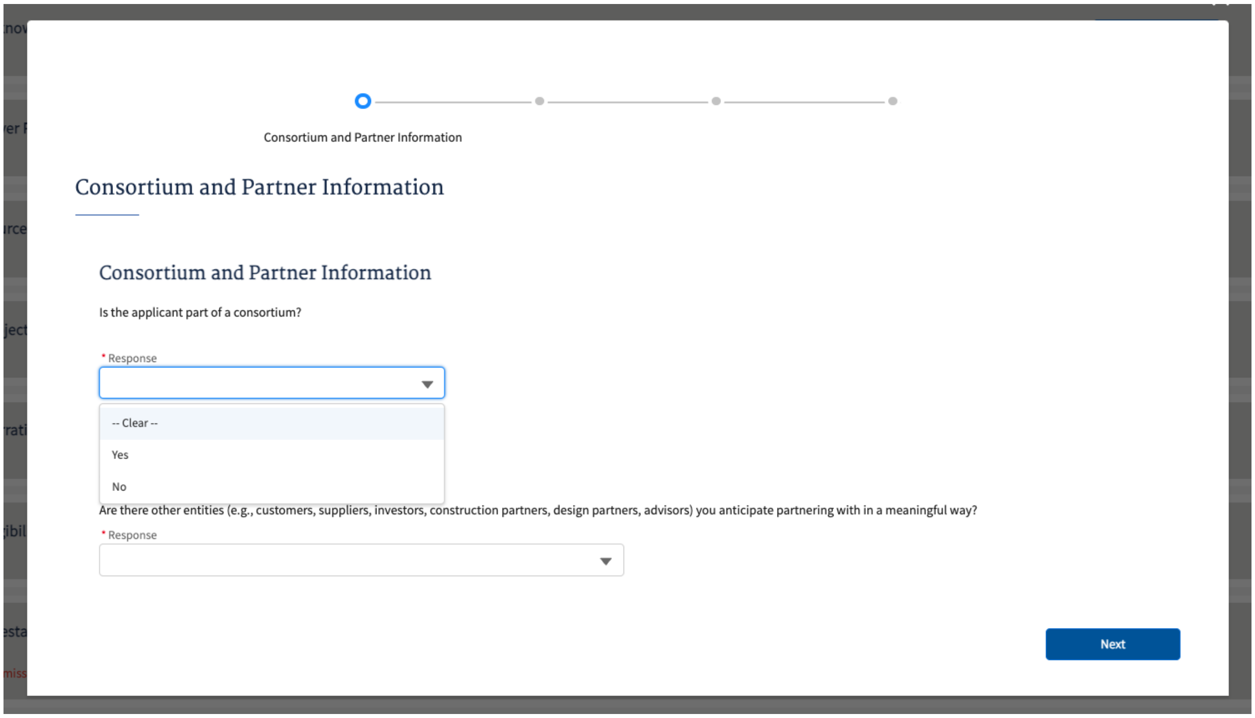
Is the applicant part of a consortium?

* Response

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response



Consortium and Partner Information

Consortium and Partner Information

Is the applicant part of a consortium?

* Response

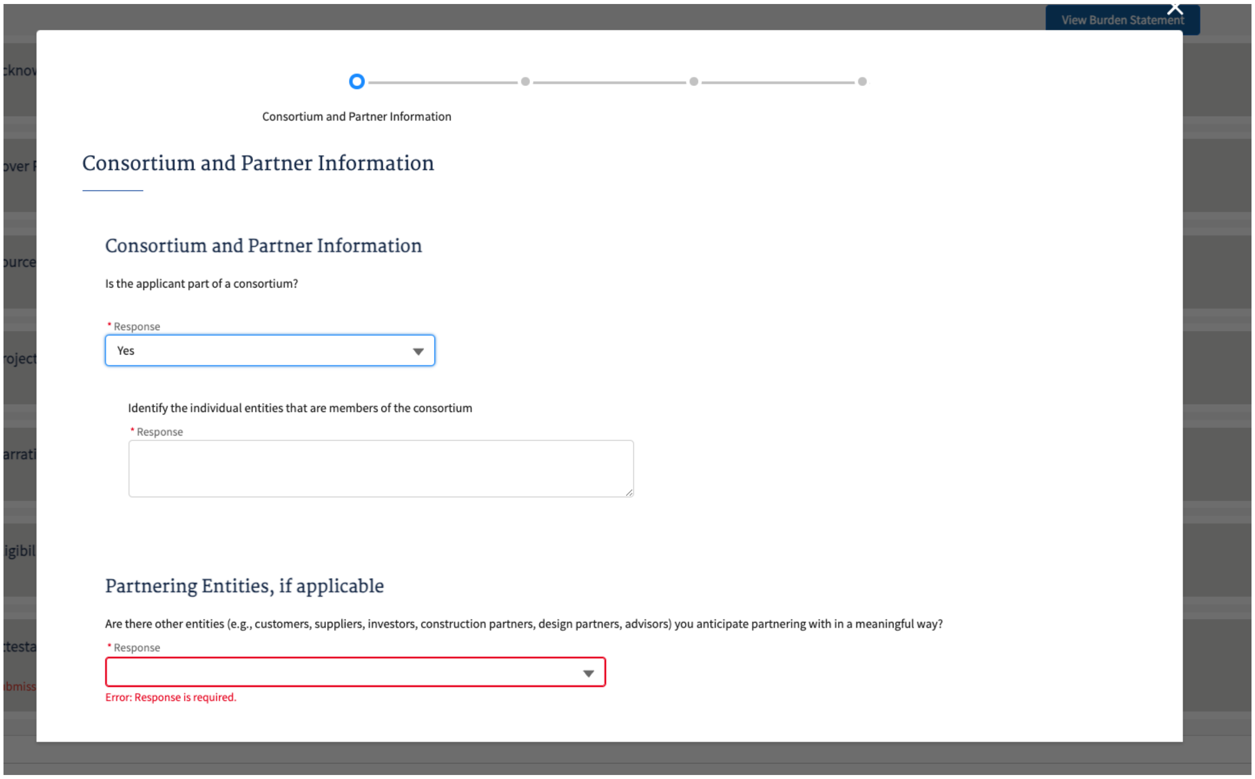
Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

Picklist: Is the applicant part of a consortium?
Picklist Values:

- Yes
- No

Is the applicant part of a consortium? Response is *Yes* prompts *Identify the individual entities that are members of the consortium*



Consortium and Partner Information

Consortium and Partner Information

Is the applicant part of a consortium?

* Response

Yes

Identify the individual entities that are members of the consortium

* Response

Partnering Entities, if applicable

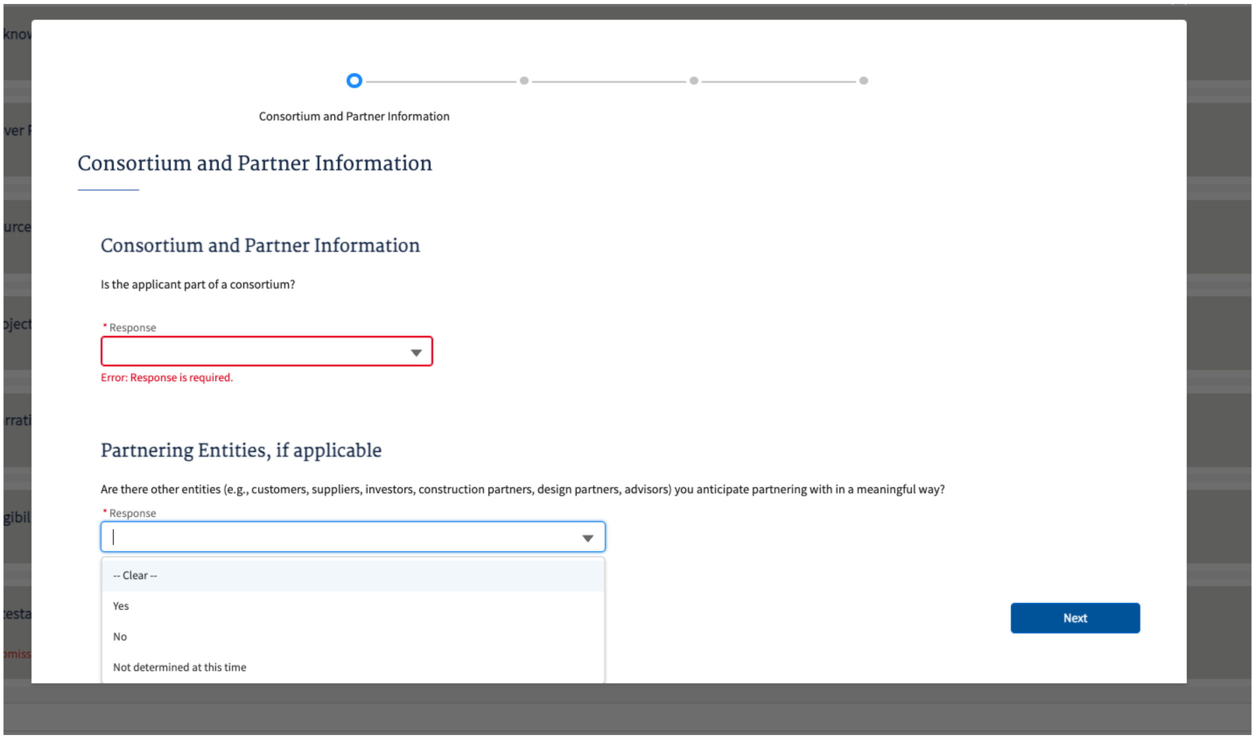
Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

Error: Response is required.

Partnering Entities, if Applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?



Consortium and Partner Information

Consortium and Partner Information

Is the applicant part of a consortium?

* Response

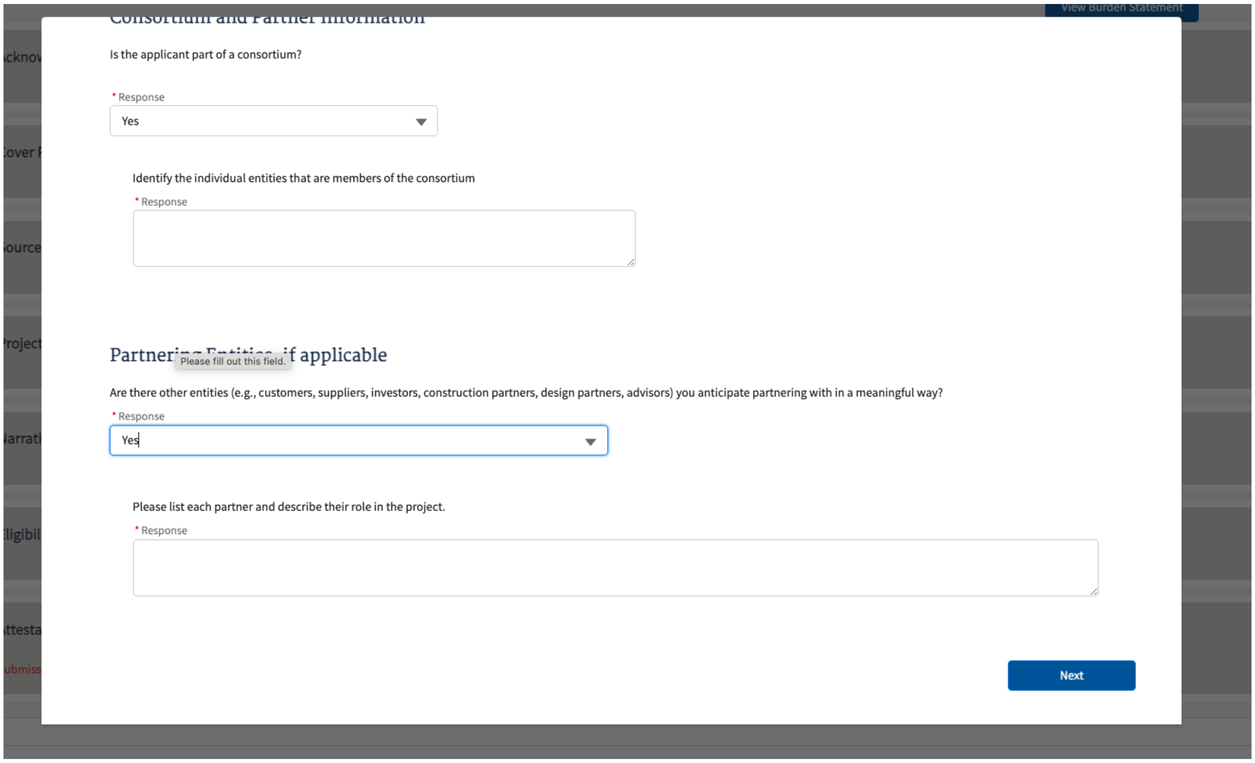
Error: Response is required.

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

* Response

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way? Response of *Yes* prompts *Please list each partner and describe their role in the project*



Consortium and Partner Information

Is the applicant part of a consortium?

* Response

Yes

Identify the individual entities that are members of the consortium

* Response

Partnering Entities, if applicable

Are there other entities (e.g., customers, suppliers, investors, construction partners, design partners, advisors) you anticipate partnering with in a meaningful way?

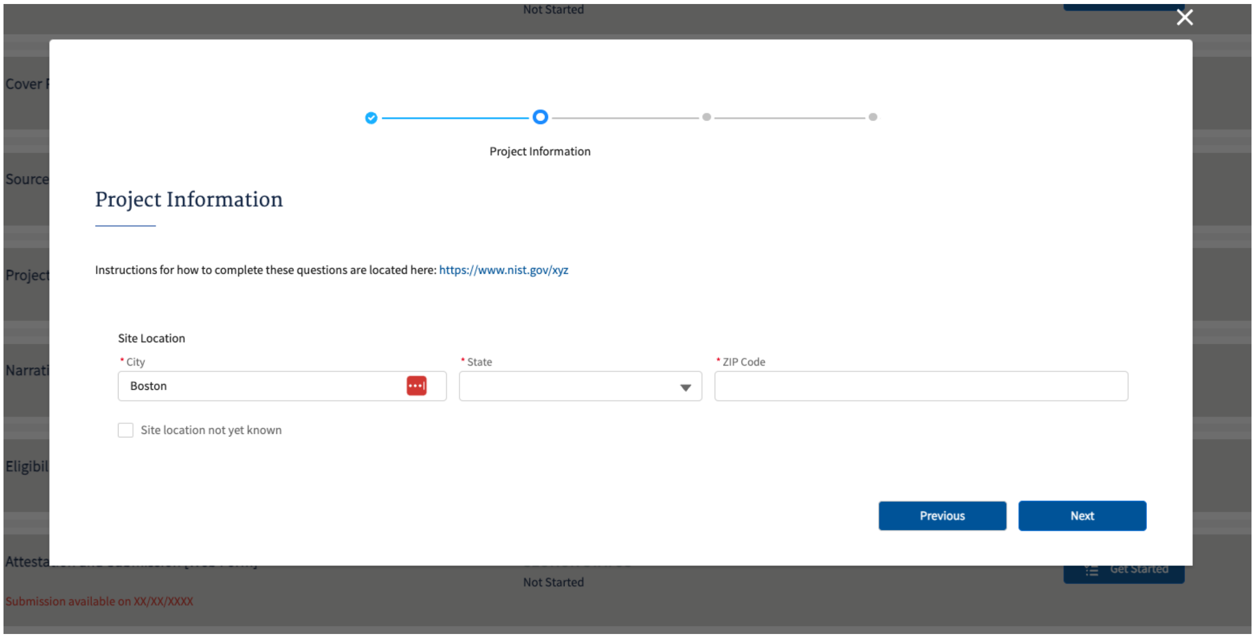
* Response

Yes

Please list each partner and describe their role in the project.

* Response

Project Information



Project Information

Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

Site Location

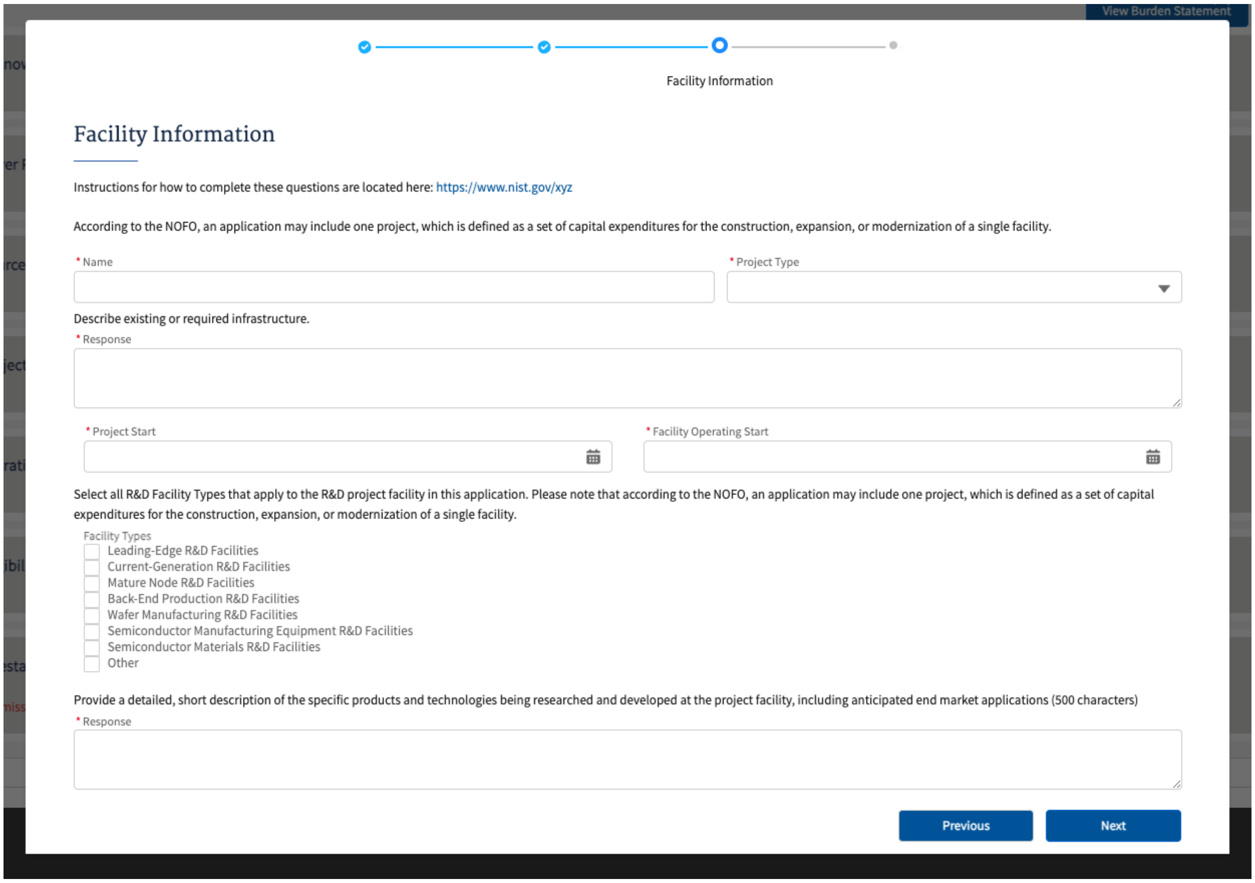
* City: Boston

* State:

* ZIP Code:

☐ Site location not yet known

Facility Information



Facility Information

Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

According to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

* Name	* Project Type

Describe existing or required infrastructure.

* Response

* Project Start	* Facility Operating Start

Select all R&D Facility Types that apply to the R&D project facility in this application. Please note that according to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

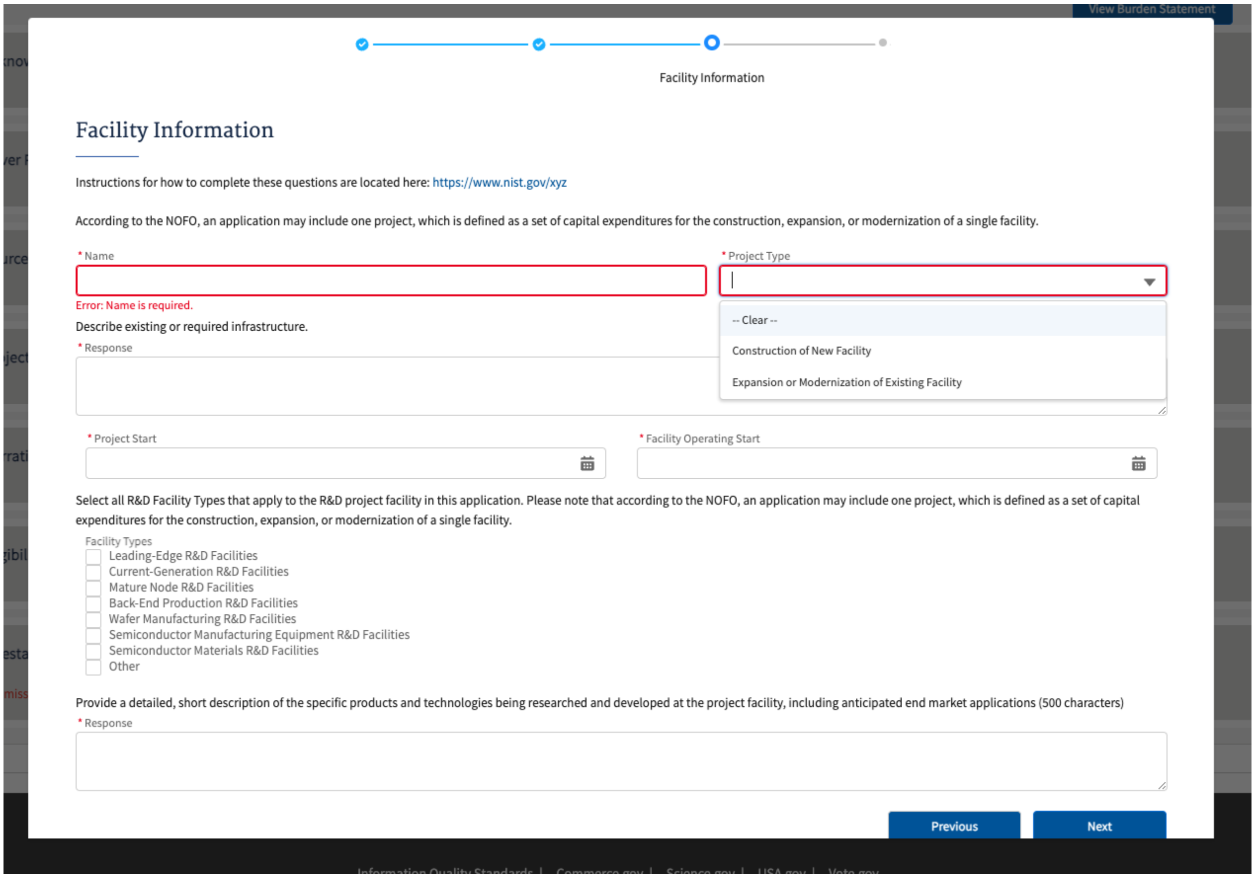
Facility Types

- ☐ Leading-Edge R&D Facilities
- ☐ Current-Generation R&D Facilities
- ☐ Mature Node R&D Facilities
- ☐ Back-End Production R&D Facilities
- ☐ Wafer Manufacturing R&D Facilities
- ☐ Semiconductor Manufacturing Equipment R&D Facilities
- ☐ Semiconductor Materials R&D Facilities
- ☐ Other

Provide a detailed, short description of the specific products and technologies being researched and developed at the project facility, including anticipated end market applications (500 characters)

* Response

Project Type



Facility Information

Instructions for how to complete these questions are located here: https://www.nist.gov/xyz

According to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

* Name

Error: Name is required.

* Project Type

-- Clear --
Construction of New Facility
Expansion or Modernization of Existing Facility

Describe existing or required infrastructure.

* Response

* Project Start

* Facility Operating Start

Select all R&D Facility Types that apply to the R&D project facility in this application. Please note that according to the NOFO, an application may include one project, which is defined as a set of capital expenditures for the construction, expansion, or modernization of a single facility.

Facility Types
☐ Leading-Edge R&D Facilities
☐ Current-Generation R&D Facilities
☐ Mature Node R&D Facilities
☐ Back-End Production R&D Facilities
☐ Wafer Manufacturing R&D Facilities
☐ Semiconductor Manufacturing Equipment R&D Facilities
☐ Semiconductor Materials R&D Facilities
☐ Other

Provide a detailed, short description of the specific products and technologies being researched and developed at the project facility, including anticipated end market applications (500 characters)

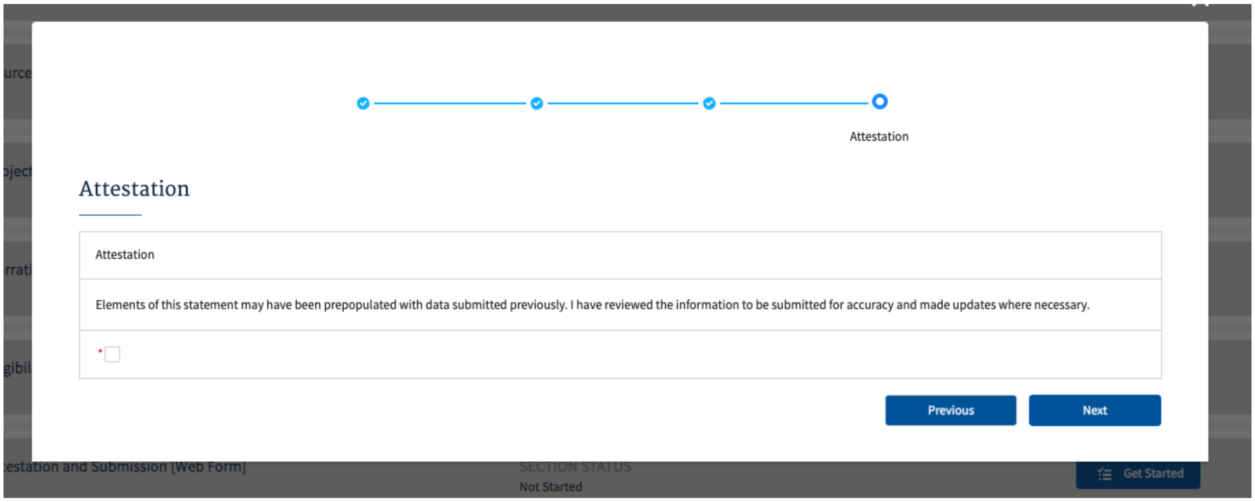
* Response

Picklist: Project Type

Picklist Values:

- Construction of New Facility
- Expansion or Modernization of Existing Facility

Attestation



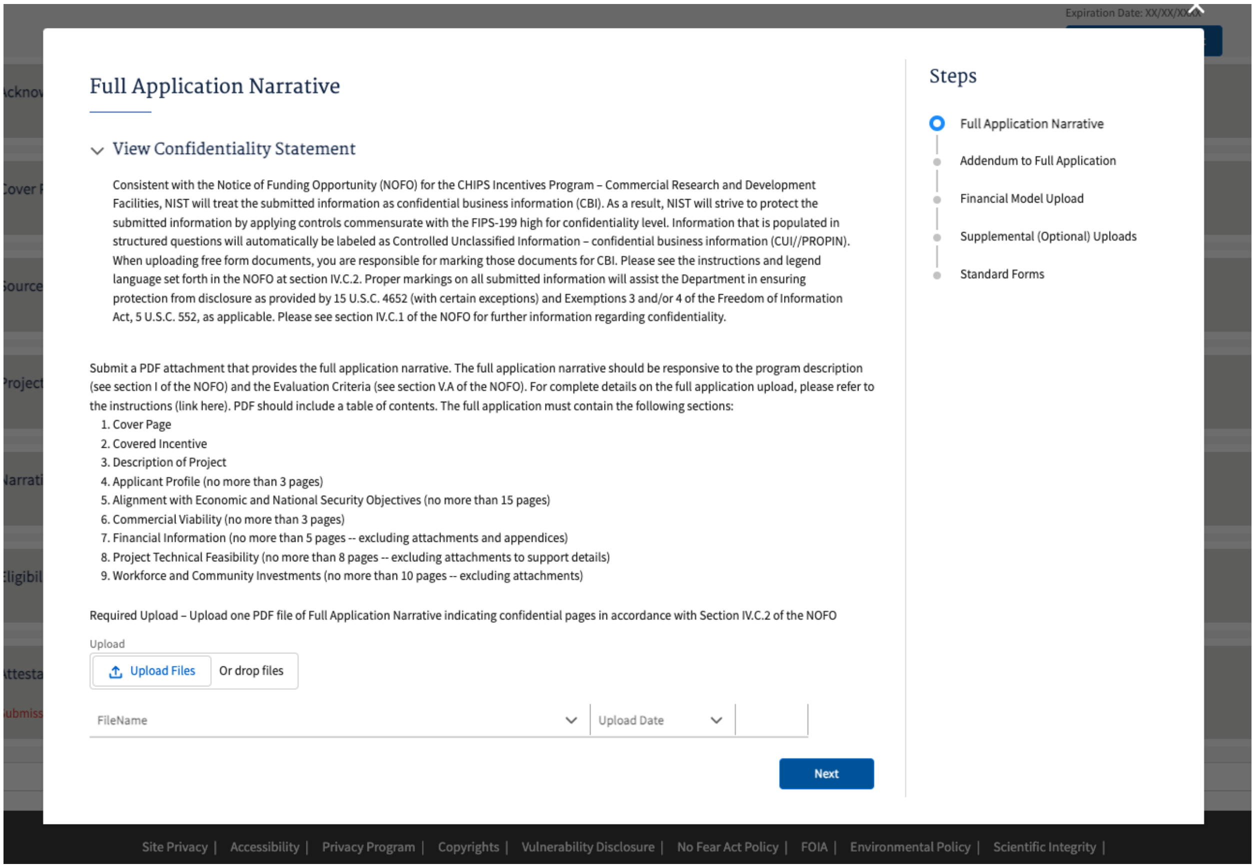
Attestation

Attestation

Elements of this statement may have been prepopulated with data submitted previously. I have reviewed the information to be submitted for accuracy and made updates where necessary.

* ☐

Narrative Uploads



Full Application Narrative

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

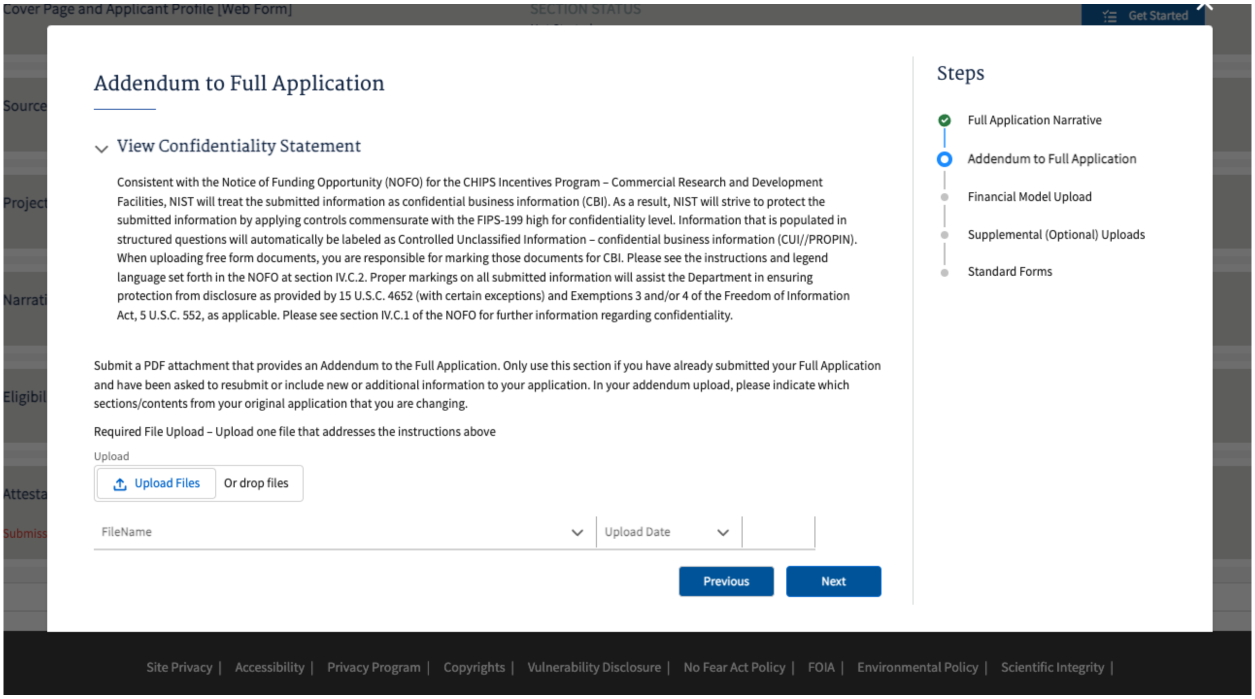
Submit a PDF attachment that provides the full application narrative. The full application narrative should be responsive to the program description (see section I of the NOFO) and the Evaluation Criteria (see section V.A of the NOFO). For complete details on the full application upload, please refer to the instructions (link here). PDF should include a table of contents. The full application must contain the following sections:

1. Cover Page
2. Covered Incentive
3. Description of Project
4. Applicant Profile (no more than 3 pages)
5. Alignment with Economic and National Security Objectives (no more than 15 pages)
6. Commercial Viability (no more than 3 pages)
7. Financial Information (no more than 5 pages -- excluding attachments and appendices)
8. Project Technical Feasibility (no more than 8 pages -- excluding attachments to support details)
9. Workforce and Community Investments (no more than 10 pages -- excluding attachments)

Required Upload – Upload one PDF file of Full Application Narrative indicating confidential pages in accordance with Section IV.C.2 of the NOFO

Upload

Addendum to Full Application



Addendum to Full Application

View Confidentiality Statement

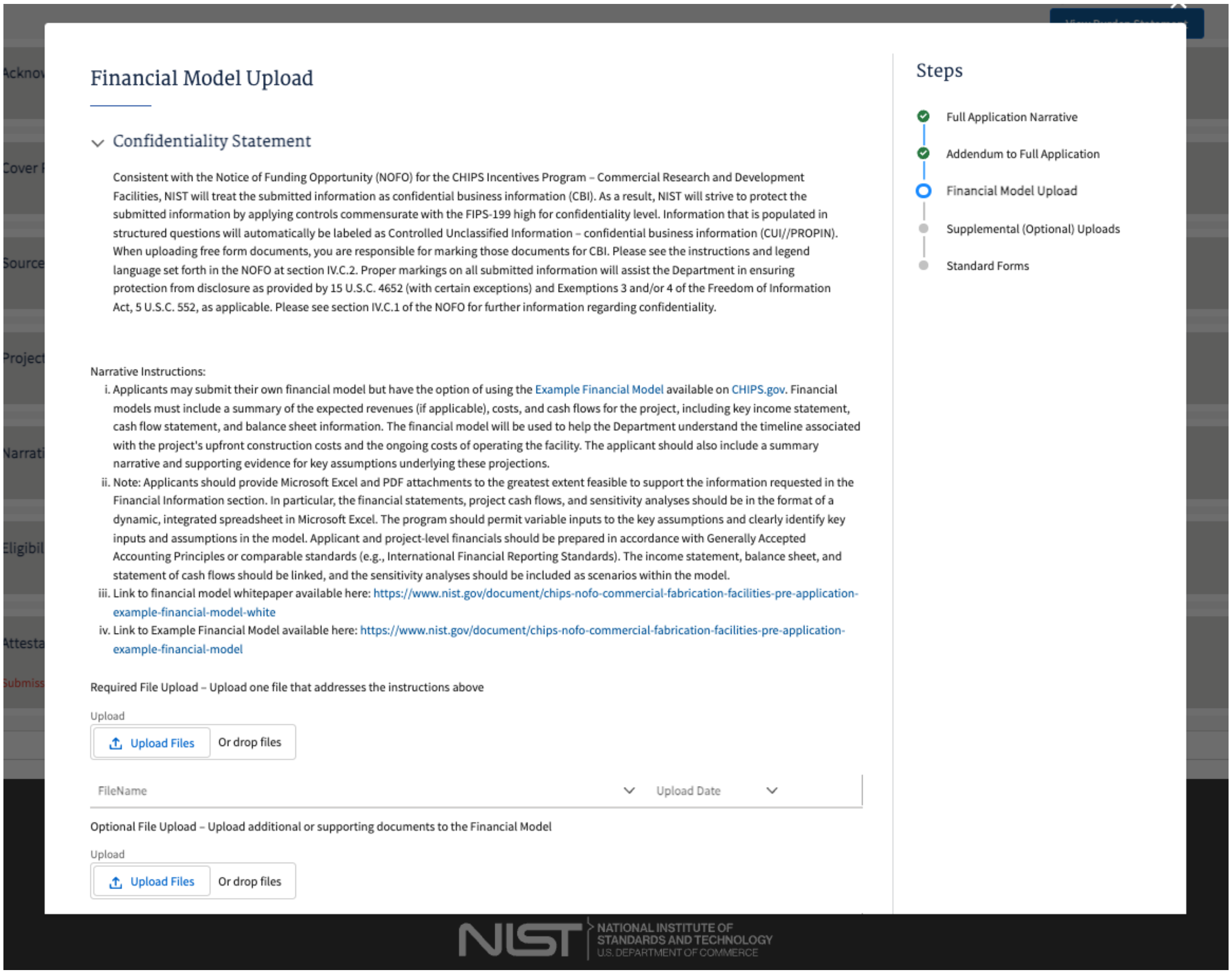
Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Submit a PDF attachment that provides an Addendum to the Full Application. Only use this section if you have already submitted your Full Application and have been asked to resubmit or include new or additional information to your application. In your addendum upload, please indicate which sections/contents from your original application that you are changing.

Required File Upload – Upload one file that addresses the instructions above

Steps

Financial Model Upload



Financial Model Upload

Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Narrative Instructions:

i. Applicants may submit their own financial model but have the option of using the Example Financial Model available on CHIPS.gov. Financial models must include a summary of the expected revenues (if applicable), costs, and cash flows for the project, including key income statement, cash flow statement, and balance sheet information. The financial model will be used to help the Department understand the timeline associated with the project's upfront construction costs and the ongoing costs of operating the facility. The applicant should also include a summary narrative and supporting evidence for key assumptions underlying these projections.

ii. Note: Applicants should provide Microsoft Excel and PDF attachments to the greatest extent feasible to support the information requested in the Financial Information section. In particular, the financial statements, project cash flows, and sensitivity analyses should be in the format of a dynamic, integrated spreadsheet in Microsoft Excel. The program should permit variable inputs to the key assumptions and clearly identify key inputs and assumptions in the model. Applicant and project-level financials should be prepared in accordance with Generally Accepted Accounting Principles or comparable standards (e.g., International Financial Reporting Standards). The income statement, balance sheet, and statement of cash flows should be linked, and the sensitivity analyses should be included as scenarios within the model.

iii. Link to financial model whitepaper available here: https://www.nist.gov/document/chips-nofo-commercial-fabrication-facilities-pre-application-example-financial-model-white

iv. Link to Example Financial Model available here: https://www.nist.gov/document/chips-nofo-commercial-fabrication-facilities-pre-application-example-financial-model

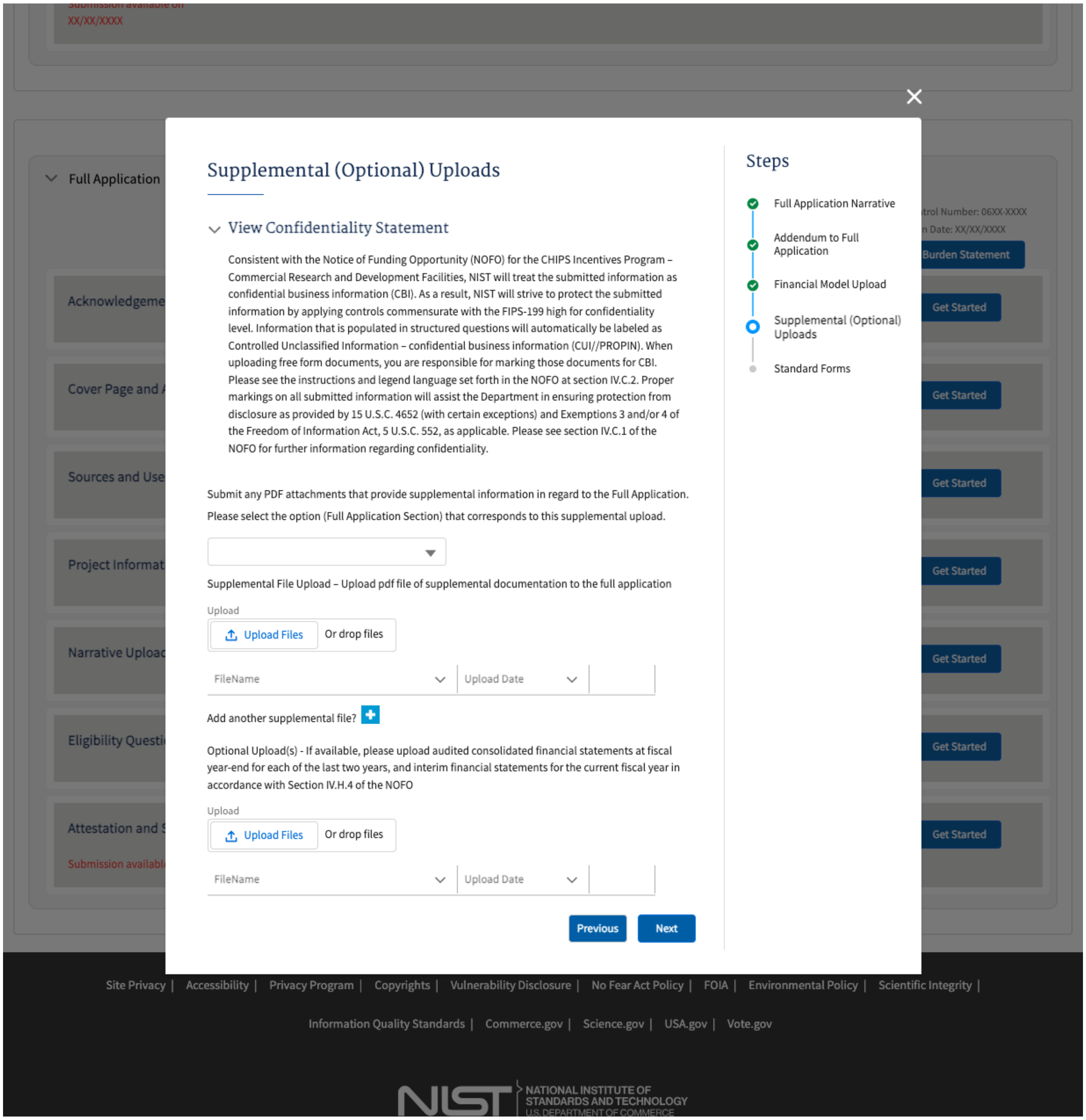
Required File Upload – Upload one file that addresses the instructions above

Upload

Optional File Upload – Upload additional or supporting documents to the Financial Model

Upload

Supplemental (Optional) Uploads



Supplemental (Optional) Uploads

View Confidentiality Statement

Consistent with the Notice of Funding Opportunity (NOFO) for the CHIPS Incentives Program – Commercial Research and Development Facilities, NIST will treat the submitted information as confidential business information (CBI). As a result, NIST will strive to protect the submitted information by applying controls commensurate with the FIPS-199 high for confidentiality level. Information that is populated in structured questions will automatically be labeled as Controlled Unclassified Information – confidential business information (CUI//PROPIN). When uploading free form documents, you are responsible for marking those documents for CBI. Please see the instructions and legend language set forth in the NOFO at section IV.C.2. Proper markings on all submitted information will assist the Department in ensuring protection from disclosure as provided by 15 U.S.C. 4652 (with certain exceptions) and Exemptions 3 and/or 4 of the Freedom of Information Act, 5 U.S.C. 552, as applicable. Please see section IV.C.1 of the NOFO for further information regarding confidentiality.

Submit any PDF attachments that provide supplemental information in regard to the Full Application.

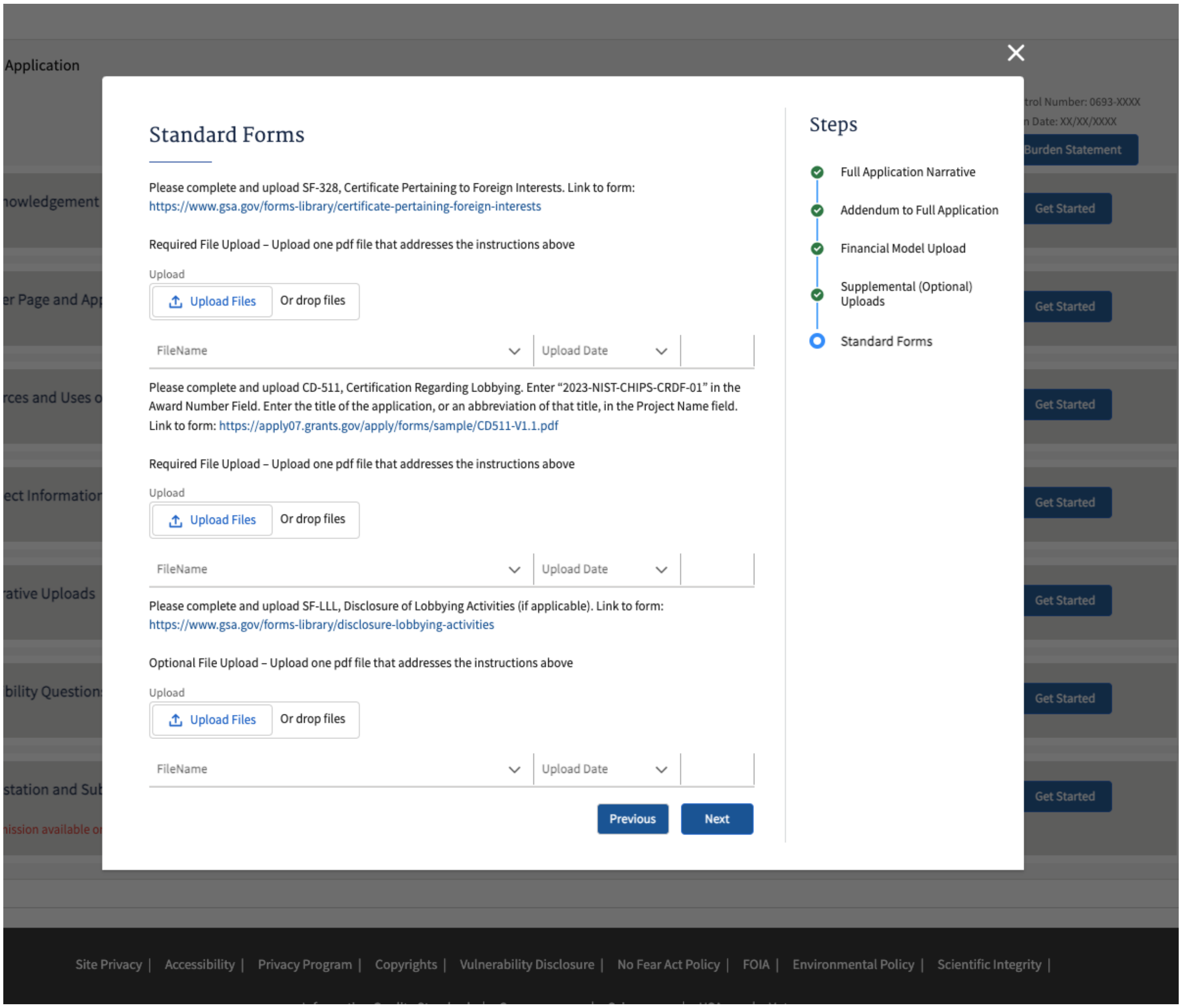
Please select the option (Full Application Section) that corresponds to this supplemental upload.

Supplemental File Upload – Upload pdf file of supplemental documentation to the full application

Add another supplemental file?

Optional Upload(s) - If available, please upload audited consolidated financial statements at fiscal year-end for each of the last two years, and interim financial statements for the current fiscal year in accordance with Section IV.H.4 of the NOFO

Standard Forms



Standard Forms

Please complete and upload SF-328, Certificate Pertaining to Foreign Interests. Link to form: https://www.gsa.gov/forms-library/certificate-pertaining-foreign-interests

Required File Upload – Upload one pdf file that addresses the instructions above

Please complete and upload CD-511, Certification Regarding Lobbying. Enter “2023-NIST-CHIPS-CRDF-01” in the Award Number Field. Enter the title of the application, or an abbreviation of that title, in the Project Name field. Link to form: https://apply07.grants.gov/apply/forms/sample/CD511-V1.1.pdf

Required File Upload – Upload one pdf file that addresses the instructions above

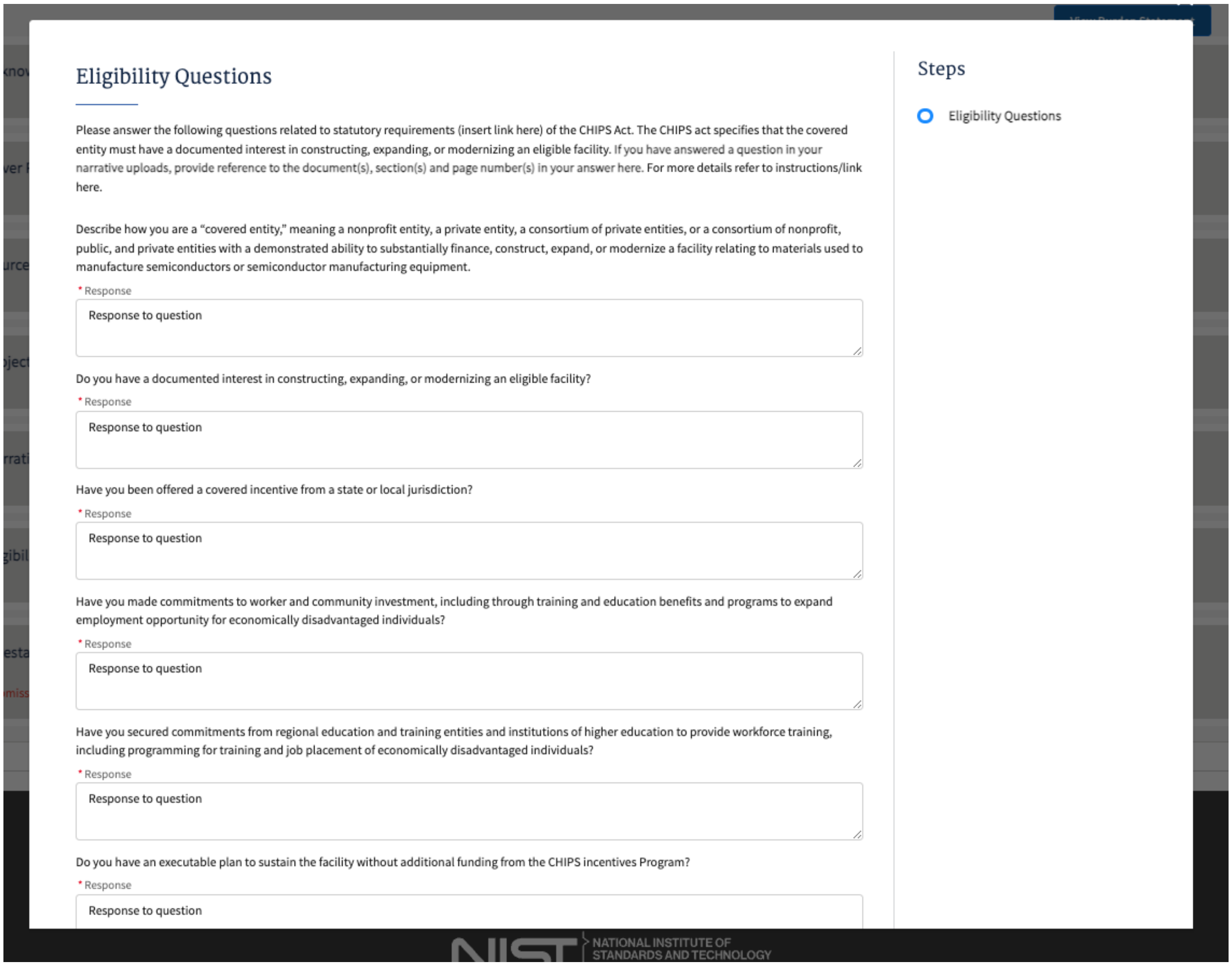
Please complete and upload SF-LLL, Disclosure of Lobbying Activities (if applicable). Link to form: https://www.gsa.gov/forms-library/disclosure-lobbying-activities

Optional File Upload – Upload one pdf file that addresses the instructions above

Steps

- ✓ Full Application Narrative
- ✓ Addendum to Full Application
- ✓ Financial Model Upload
- ✓ Supplemental (Optional) Uploads
- ○ Standard Forms

Eligibility Questions



Eligibility Questions

Please answer the following questions related to statutory requirements (insert link here) of the CHIPS Act. The CHIPS act specifies that the covered entity must have a documented interest in constructing, expanding, or modernizing an eligible facility. If you have answered a question in your narrative uploads, provide reference to the document(s), section(s) and page number(s) in your answer here. For more details refer to instructions/link here.

Describe how you are a "covered entity," meaning a nonprofit entity, a private entity, a consortium of private entities, or a consortium of nonprofit, public, and private entities with a demonstrated ability to substantially finance, construct, expand, or modernize a facility relating to materials used to manufacture semiconductors or semiconductor manufacturing equipment.

* Response

Response to question

Do you have a documented interest in constructing, expanding, or modernizing an eligible facility?

* Response

Response to question

Have you been offered a covered incentive from a state or local jurisdiction?

* Response

Response to question

Have you made commitments to worker and community investment, including through training and education benefits and programs to expand employment opportunity for economically disadvantaged individuals?

* Response

Response to question

Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training, including programming for training and job placement of economically disadvantaged individuals?

* Response

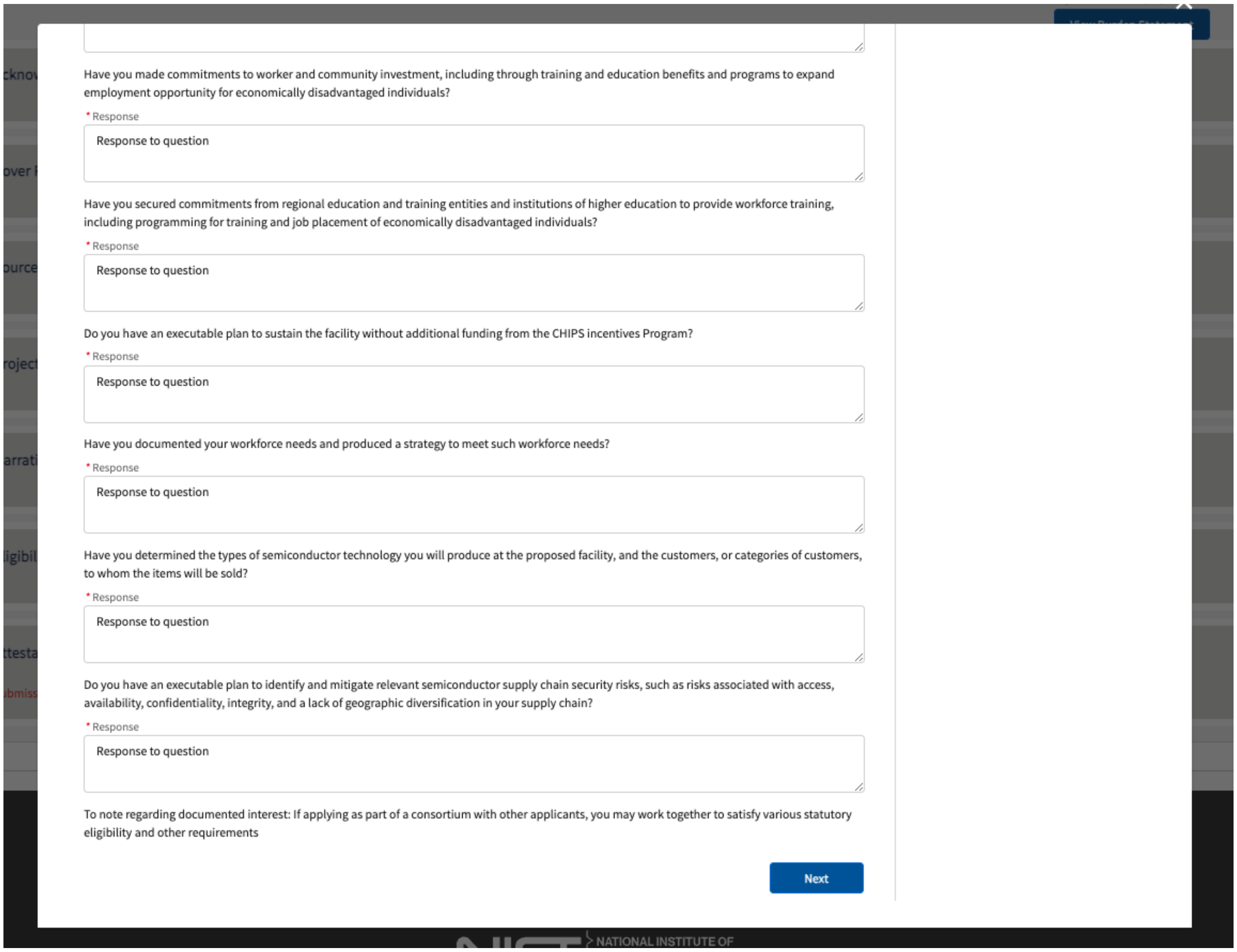
Response to question

Do you have an executable plan to sustain the facility without additional funding from the CHIPS incentives Program?

* Response

Response to question

Eligibility Question Continued



Have you made commitments to worker and community investment, including through training and education benefits and programs to expand employment opportunity for economically disadvantaged individuals?

* Response

Response to question

Have you secured commitments from regional education and training entities and institutions of higher education to provide workforce training, including programming for training and job placement of economically disadvantaged individuals?

* Response

Response to question

Do you have an executable plan to sustain the facility without additional funding from the CHIPS incentives Program?

* Response

Response to question

Have you documented your workforce needs and produced a strategy to meet such workforce needs?

* Response

Response to question

Have you determined the types of semiconductor technology you will produce at the proposed facility, and the customers, or categories of customers, to whom the items will be sold?

* Response

Response to question

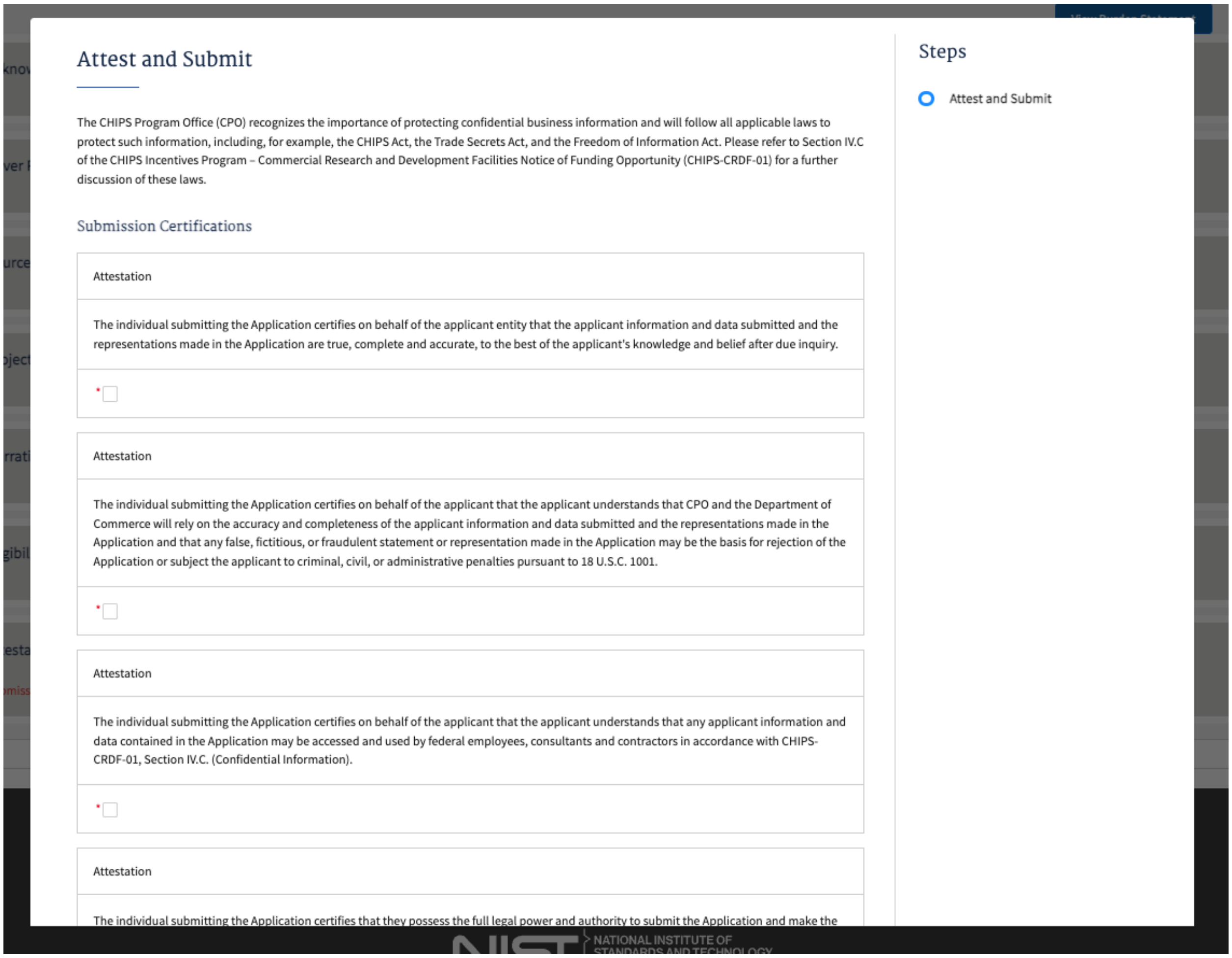
Do you have an executable plan to identify and mitigate relevant semiconductor supply chain security risks, such as risks associated with access, availability, confidentiality, integrity, and a lack of geographic diversification in your supply chain?

* Response

Response to question

To note regarding documented interest: If applying as part of a consortium with other applicants, you may work together to satisfy various statutory eligibility and other requirements

Attest and Submit



Attest and Submit

The CHIPS Program Office (CPO) recognizes the importance of protecting confidential business information and will follow all applicable laws to protect such information, including, for example, the CHIPS Act, the Trade Secrets Act, and the Freedom of Information Act. Please refer to Section IV.C of the CHIPS Incentives Program – Commercial Research and Development Facilities Notice of Funding Opportunity (CHIPS-CRDF-01) for a further discussion of these laws.

Submission Certifications

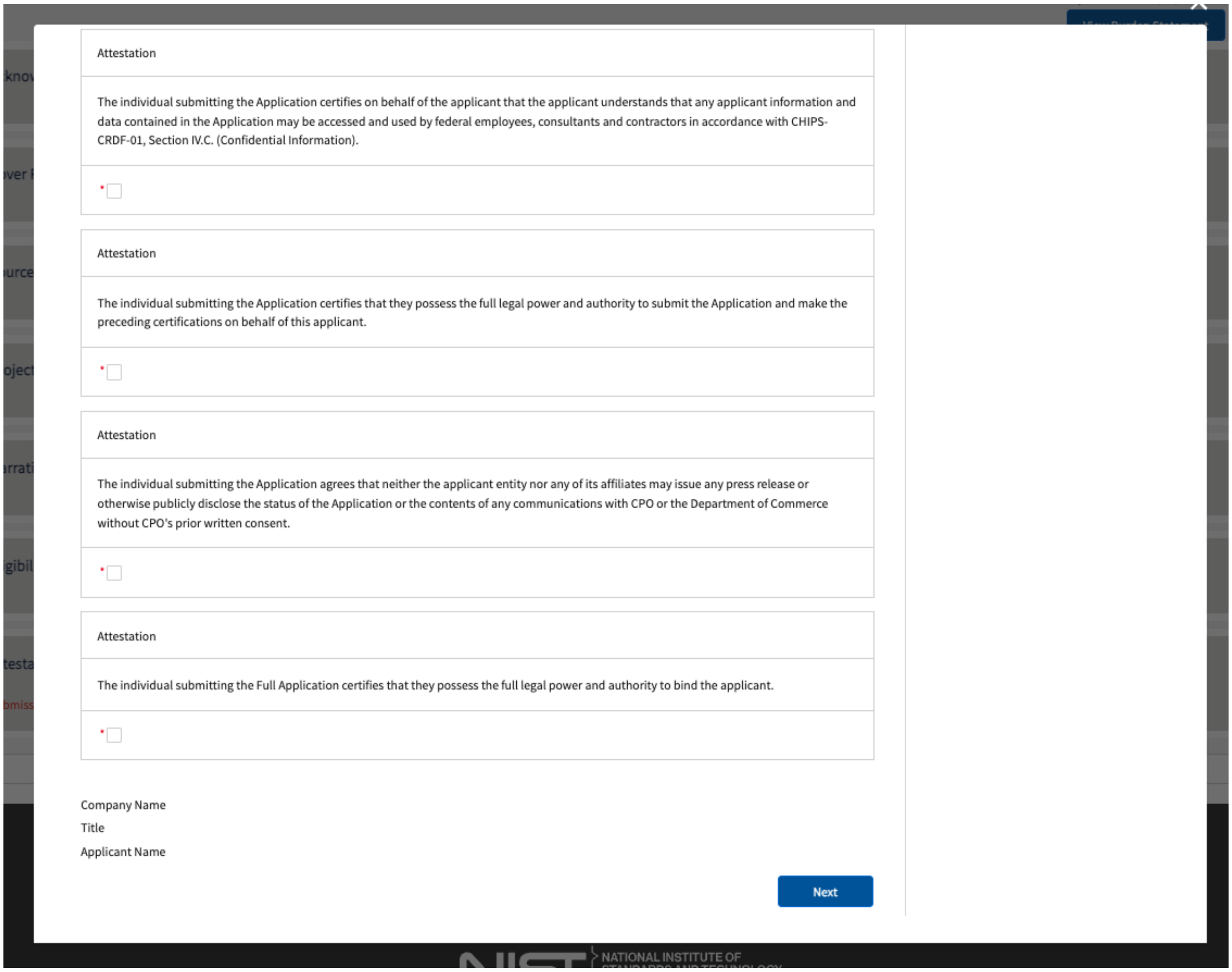
Attestation
The individual submitting the Application certifies on behalf of the applicant entity that the applicant information and data submitted and the representations made in the Application are true, complete and accurate, to the best of the applicant's knowledge and belief after due inquiry.
* ☐

Attestation
The individual submitting the Application certifies on behalf of the applicant that the applicant understands that CPO and the Department of Commerce will rely on the accuracy and completeness of the applicant information and data submitted and the representations made in the Application and that any false, fictitious, or fraudulent statement or representation made in the Application may be the basis for rejection of the Application or subject the applicant to criminal, civil, or administrative penalties pursuant to 18 U.S.C. 1001.
* ☐

Attestation
The individual submitting the Application certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Application may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-CRDF-01, Section IV.C. (Confidential Information).
* ☐

Attestation
The individual submitting the Application certifies that they possess the full legal power and authority to submit the Application and make the

Attest and Submit Continued



Attestation

The individual submitting the Application certifies on behalf of the applicant that the applicant understands that any applicant information and data contained in the Application may be accessed and used by federal employees, consultants and contractors in accordance with CHIPS-CRDF-01, Section IV.C. (Confidential Information).

* ☐

Attestation

The individual submitting the Application certifies that they possess the full legal power and authority to submit the Application and make the preceding certifications on behalf of this applicant.

* ☐

Attestation

The individual submitting the Application agrees that neither the applicant entity nor any of its affiliates may issue any press release or otherwise publicly disclose the status of the Application or the contents of any communications with CPO or the Department of Commerce without CPO's prior written consent.

* ☐

Attestation

The individual submitting the Full Application certifies that they possess the full legal power and authority to bind the applicant.

* ☐

Company Name

Title

Applicant Name